

Processing of High Conductivity Microchannel Linear Cellular Materials

Joe Cochran

Lightweight Structures Group

Other PIs: Jim Lee, Dave McDowell and Tom Sanders

Students: Ben Church, Justin Clark, Ben Dempsey, Alethea (Le') Hayes,
Kevin Hurysz, Tammy McCoy, Jason Nadler, Raymond Oh, Wes Seay

School of Materials Science and Mechanical Engineering
Georgia Institute of Technology
Atlanta GA 30332-0245

Presented at the
Thermal Materials Workshop 2001
May 30-June 1, Cambridge University, Cambridge, UK

REPORT DOCUMENTATION PAGE				Form Approved OMB No. 0704-0188	
Public reporting burden for this collection of information is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing this collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing this burden to Department of Defense, Washington Headquarters Services, Directorate for Information Operations and Reports (0704-0188), 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302. Respondents should be aware that notwithstanding any other provision of law, no person shall be subject to any penalty for failing to comply with a collection of information if it does not display a currently valid OMB control number. PLEASE DO NOT RETURN YOUR FORM TO THE ABOVE ADDRESS.					
1. REPORT DATE (DD-MM-YYYY) 30-05-2001		2. REPORT TYPE Workshop Presentations		3. DATES COVERED (FROM - TO) 30-05-2001 to 01-06-2001	
4. TITLE AND SUBTITLE Processing of High Conductivity Microchannel Linear Cellular Materials Unclassified				5a. CONTRACT NUMBER	
				5b. GRANT NUMBER	
				5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S) Cochran, Joe ;				5d. PROJECT NUMBER	
				5e. TASK NUMBER	
				5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME AND ADDRESS School of Materials Science and Mechanical Engineering Georgia Institute of Technology Atlanta, GA30332-0245				8. PERFORMING ORGANIZATION REPORT NUMBER	
9. SPONSORING/MONITORING AGENCY NAME AND ADDRESS Office of Naval Research International Field Office Office of Naval Research Washington, DCxxxxx				10. SPONSOR/MONITOR'S ACRONYM(S)	
				11. SPONSOR/MONITOR'S REPORT NUMBER(S)	
12. DISTRIBUTION/AVAILABILITY STATEMENT APUBLIC RELEASE					
13. SUPPLEMENTARY NOTES See Also ADM001348, Thermal Materials Workshop 2001, held in Cambridge, UK on May 30-June 1, 2001. Additional papers can be downloaded from: http://www-mech.eng.cam.ac.uk/onr/					
14. ABSTRACT Processing of High Conductivity Microchannel Linear Cellular Materials ! Models for paste properties and LCS die designs are nearing completion. ! Quality of honeycomb extrusion has improved dramatically and defects have been minimized. ! Metallurgical properties of alloys from direct oxide reduction can approach those of conventionally processed alloys. ! Due to low pressure drops and thin walls, high efficiency heat exchangers appear feasible for LCAs in a variety of applications. ! High energy adsorption for LCM in high strength alloys has been demonstrated.					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:		17. LIMITATION OF ABSTRACT		18. NUMBER OF PAGES	
		Public Release		45	
19. NAME OF RESPONSIBLE PERSON Fenster, Lynn lfenster@dtic.mil					
a. REPORT Unclassified	b. ABSTRACT Unclassified	c. THIS PAGE Unclassified	19b. TELEPHONE NUMBER International Area Code Area Code Telephone Number 703767-9007 DSN 427-9007		
					Standard Form 298 (Rev. 8-98) Prescribed by ANSI Std Z39.18

Acknowledgements

Honeycomb Structures for Thermal Dissipation Systems



ONR Grant N0014-99-1-0852

Project Monitor - Dr. Steven Fishman

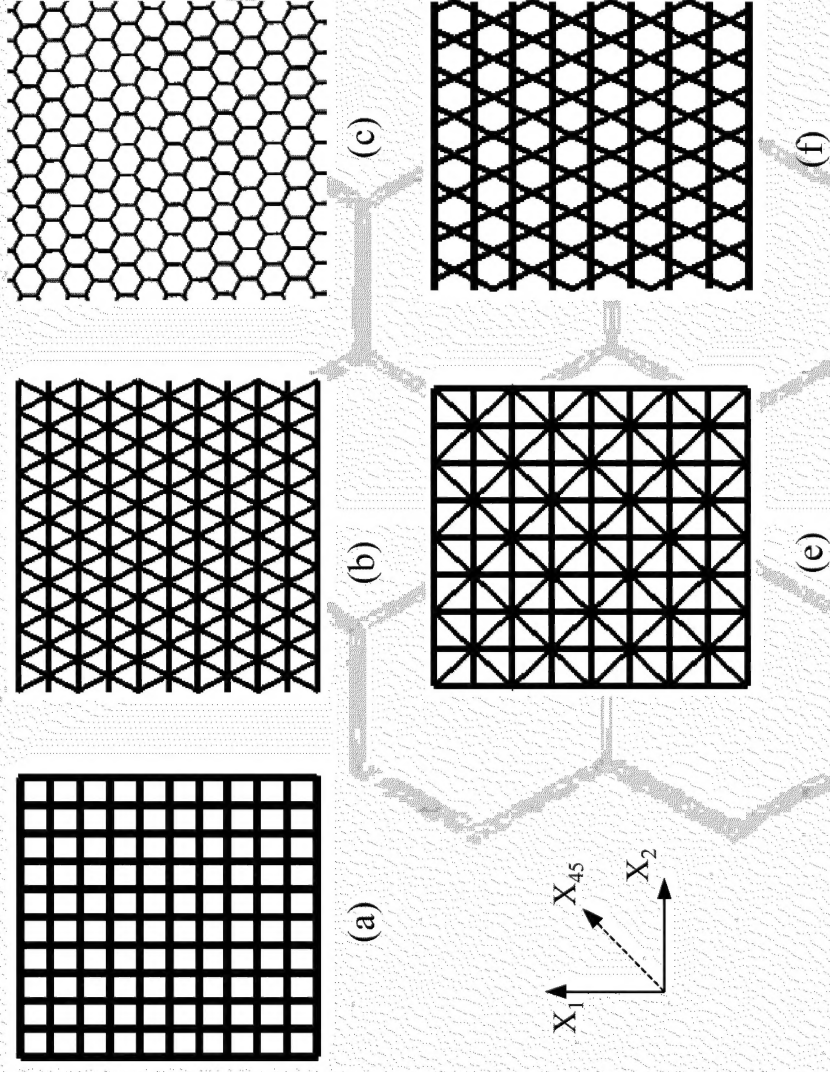
Linear Cellular Alloys for Structural Applications

DARPA-ONR Grant N00014-99-1-1016



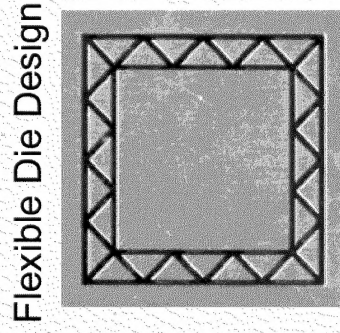
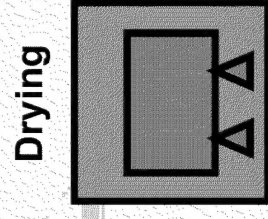
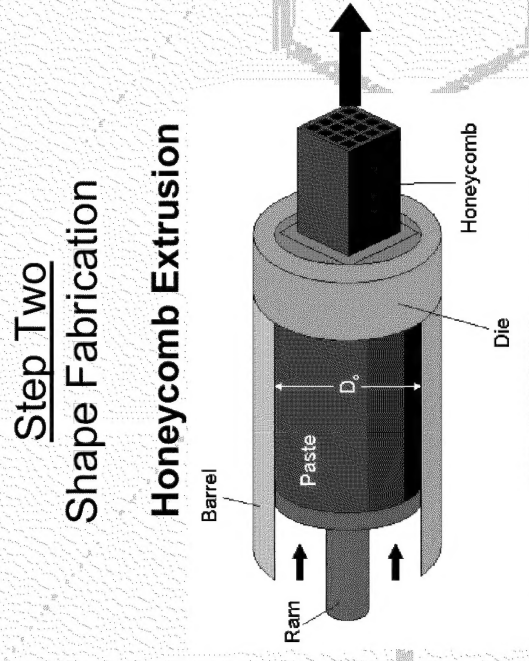
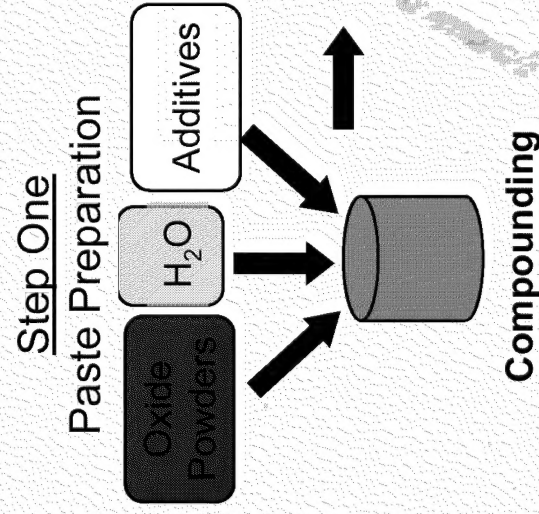
Project Monitor - Dr. Leo Christodoulou

Honeycombs with Various Cell Types

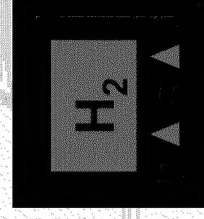
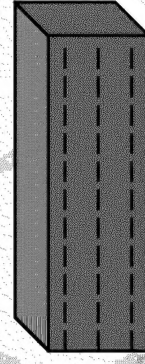


(a) square; (b) triangle; (c) hexagonal; (d) mixed triangle and square; (e) kagome

Oxide Powders Transformed into Metal Linear Cell Structures



Step Three
Direct Reduction



Direct Reduction

Material Compositions

Maraging Steels

Fe 18Ni 12Co 4Mo 1.5 Ti

from Fe_3O_4 , NiO, Co_3O_4 , MoO_3 , TiH_2

Reduction = Hydrogen at 1350 °C

- Ni Alloy - “617”

22Cr 55Ni 12Co 9Mo from Cr_2O_3 , NiO, Co_3O_4 , MoO_3

- Copper

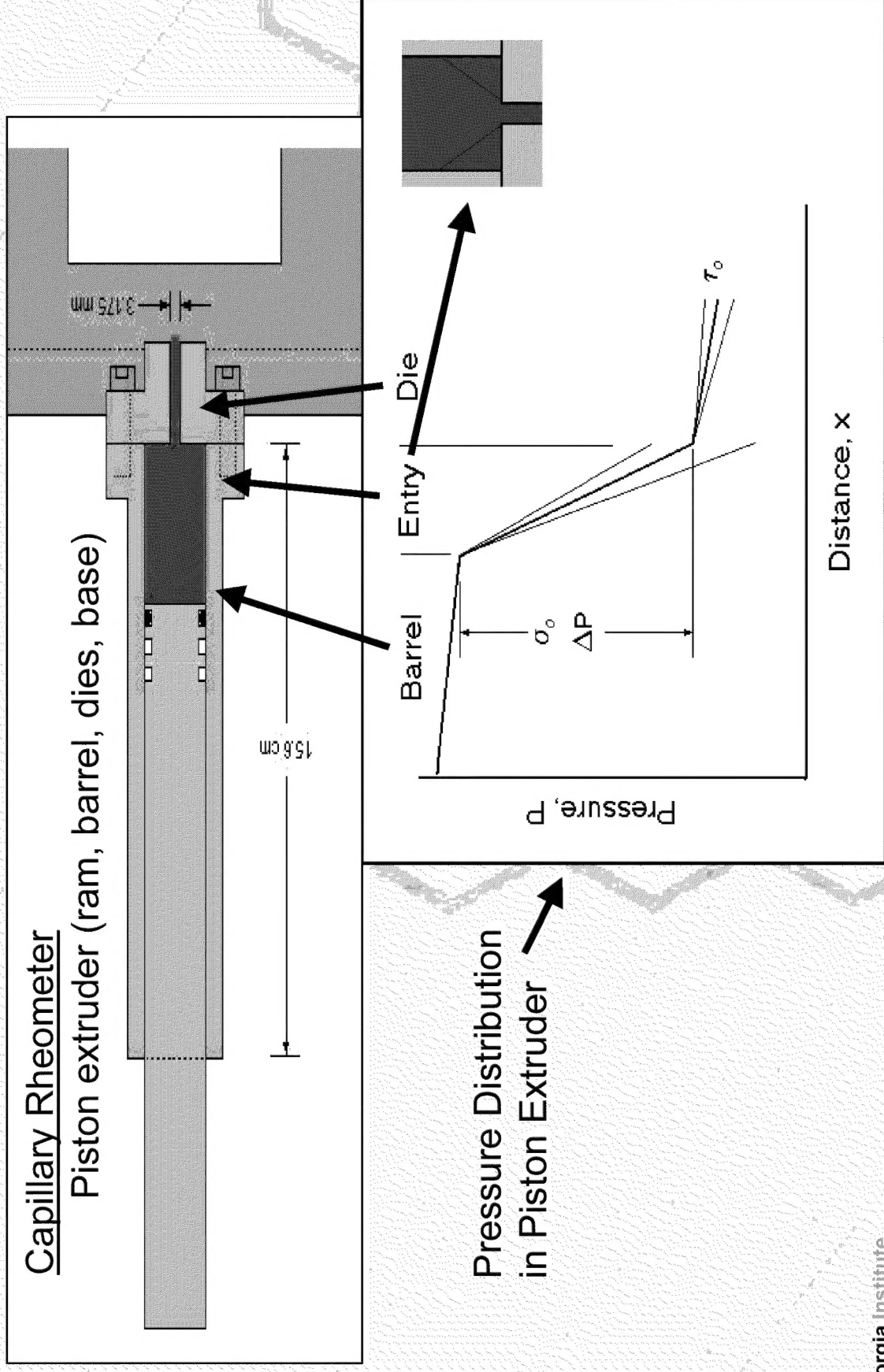
Cu, Cu 1Ni, Cu 3Ni, Cu 8Ni, Cu 3Ag from Cu_2O , NiO, AgO

- Inconel reduction process (“718”)*



*Weight Ratios

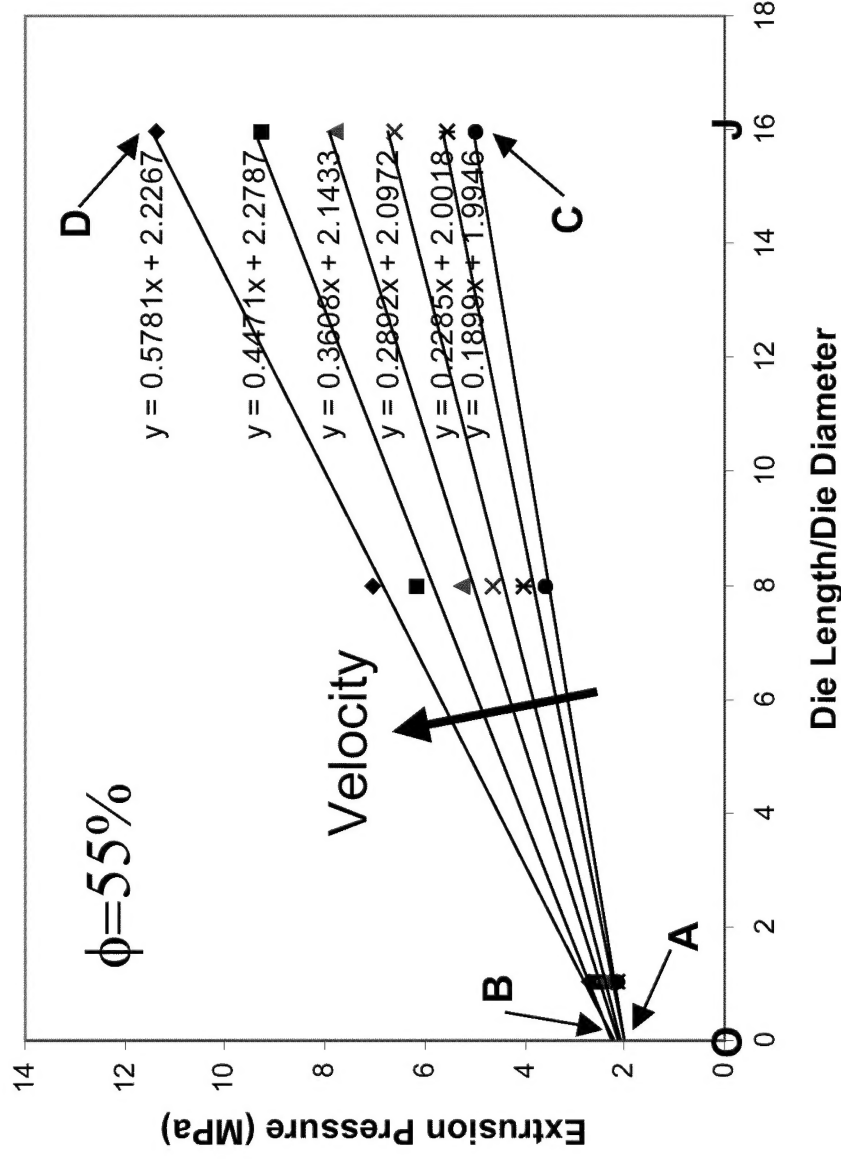
Paste Characterization



Paste Characterization

Paste Yield Stress, σ_o , and Wall Shear Stress, τ_o .

$$P = 2(\sigma_o + \alpha V) \ln \left(\frac{D_o}{D} \right) + 4(\tau_o + \beta V) \left(\frac{L}{D} \right)$$



$$\sigma_o = \frac{(OA)}{2 \ln \left(\frac{D_o}{D} \right)}$$

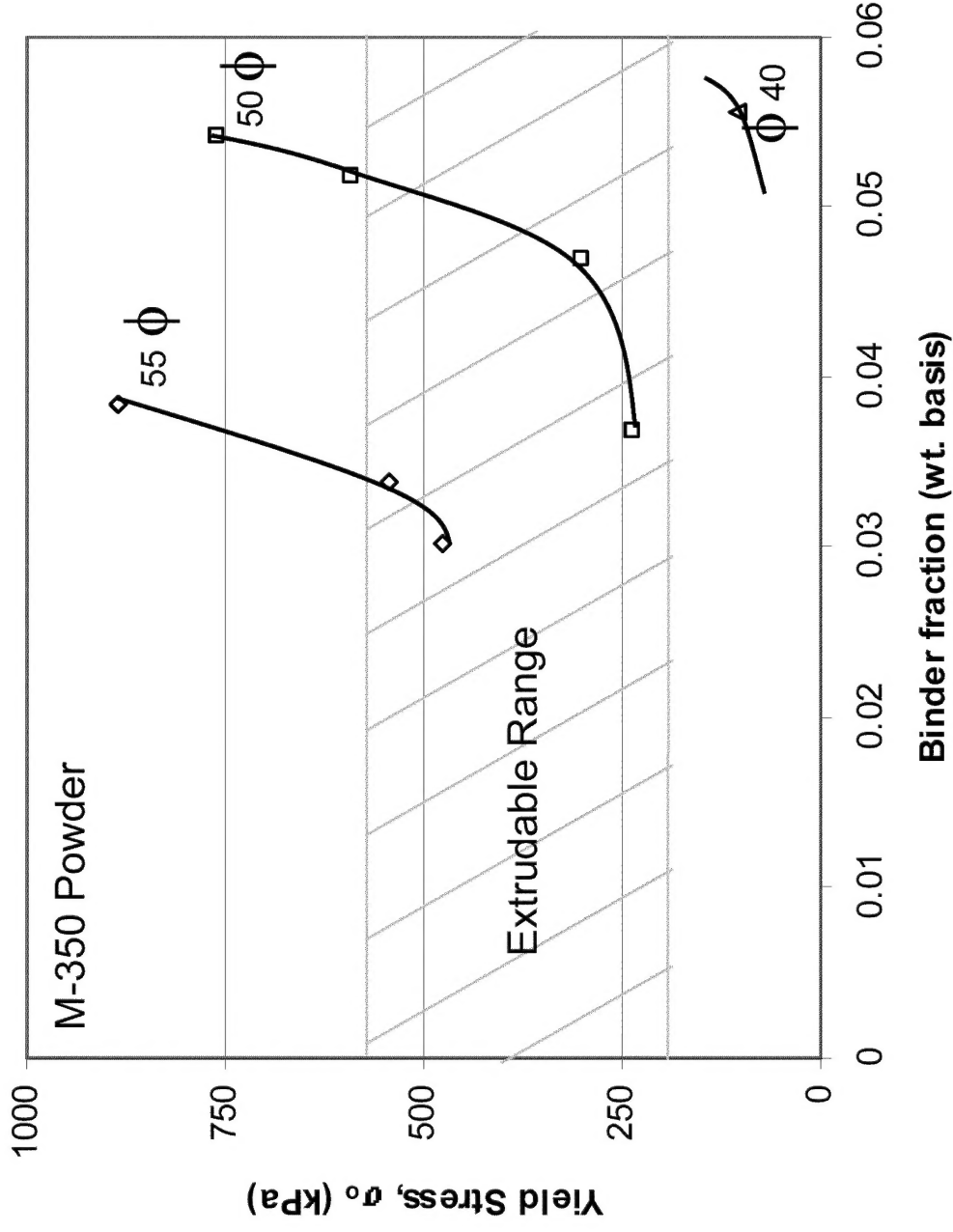
$$\tau_o = \frac{(CJ) - (OA)}{4(OJ)}$$

After Benbow
and Bridgewater

Paste Characterization

Effect of Binder and Solids Content, ϕ .

By varying binder and solids content, optimum plasticity coupled with minimum drying shrinkage and reasonable green strength can be achieved while keeping paste yield strength in the extrudable range.



Linear Cellular Die Design

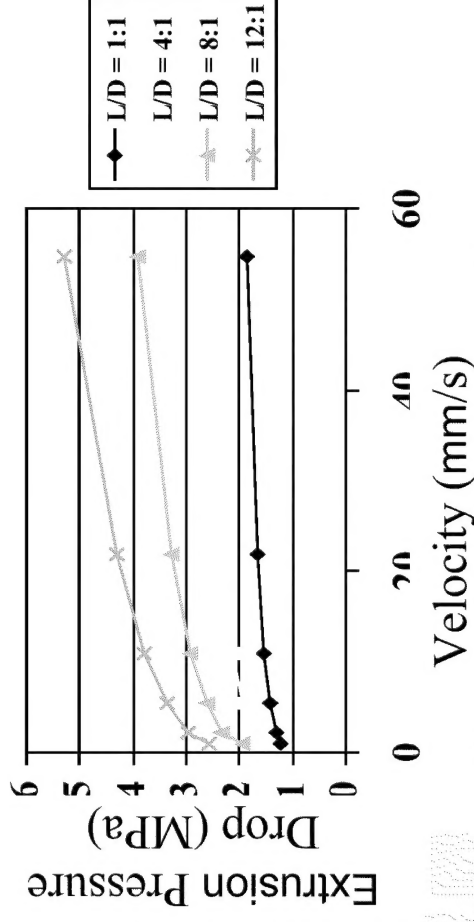
- Extrusion pressure is dependent on:
 - Extrudate velocity
 - Paste rheology
- Pressure drops result from:
 - Change in die area

$$P = (\sigma_o + \alpha V) \ln(A_o / A)$$

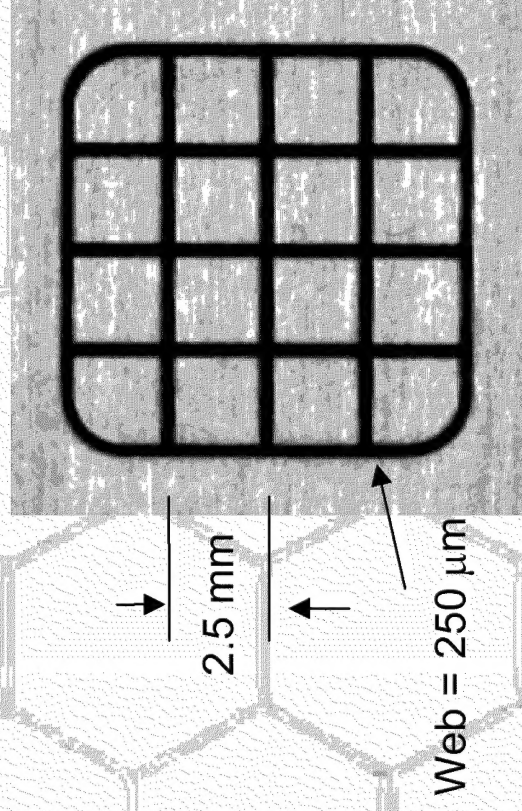
- Shear stresses from die wall

$$P = (\tau_o + \beta V)(ML / A)$$

- Utilizing these relationships, predictions for pressure drops across honeycomb dies can be made.



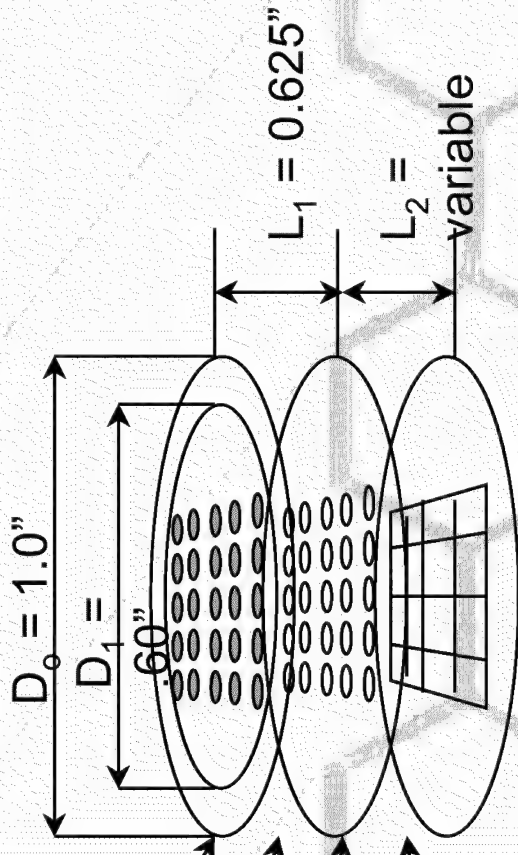
Honeycomb die for rheometer:



Linear Cellular Die Design

Square Cell Die Parameters/ Pressure Drop Modeling

- P_1 = pressure drop from area reduction in barrel to entry holes
- P_2 = pressure drop from flow through holes
- P_3 = pressure drop from area reduction in holes to slots
- P_4 = pressure drop from flow through die slots



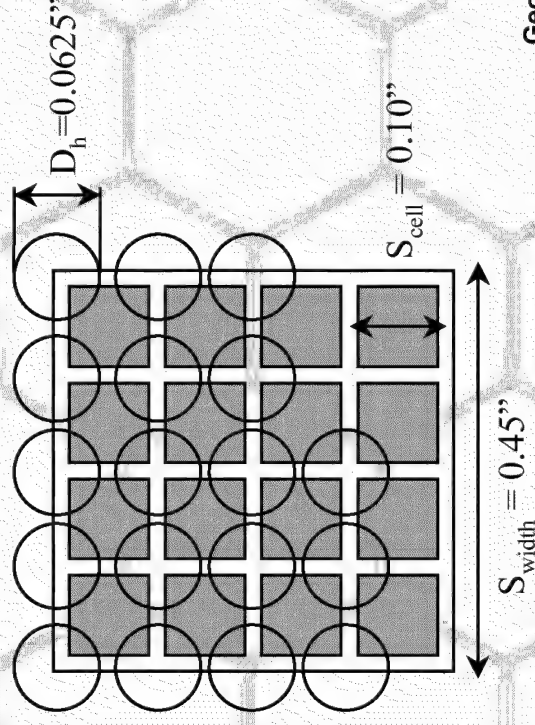
Blackburn & Böhm Equations

$$P_1 = 2\left(\sigma_o + \frac{\alpha 4Q}{\pi D_h^2}\right) + 2\left(\sigma_o + \frac{\alpha 4Q}{\pi D_h^2 N}\right) \ln\left(\frac{D_1}{D_h \sqrt{N}}\right)$$

$$P_2 = 4\left(\tau_o + \frac{\beta 4Q}{\pi D_h^2 N}\right) \left(\frac{L}{D_h}\right)$$

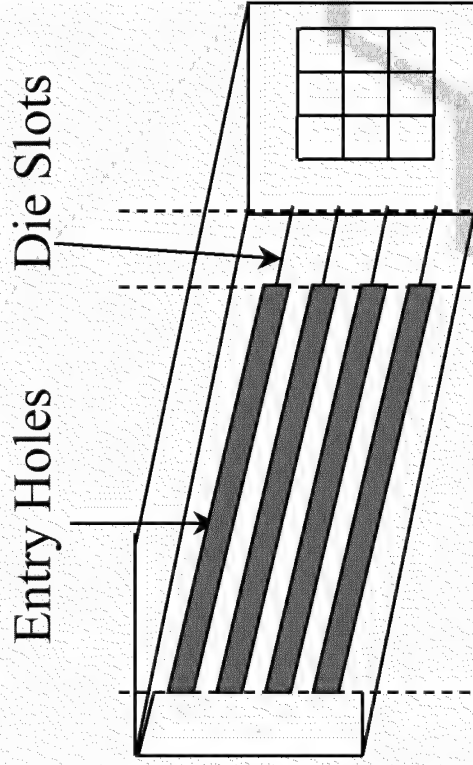
$$P_3 = \left(\sigma_o + \frac{\alpha Q}{A_s}\right) \ln\left(\frac{A_h}{A_s}\right)$$

$$P_4 = 4\left(\tau_o + \frac{\beta Q}{A_s}\right) \left(\frac{ML_2}{A_s}\right)$$



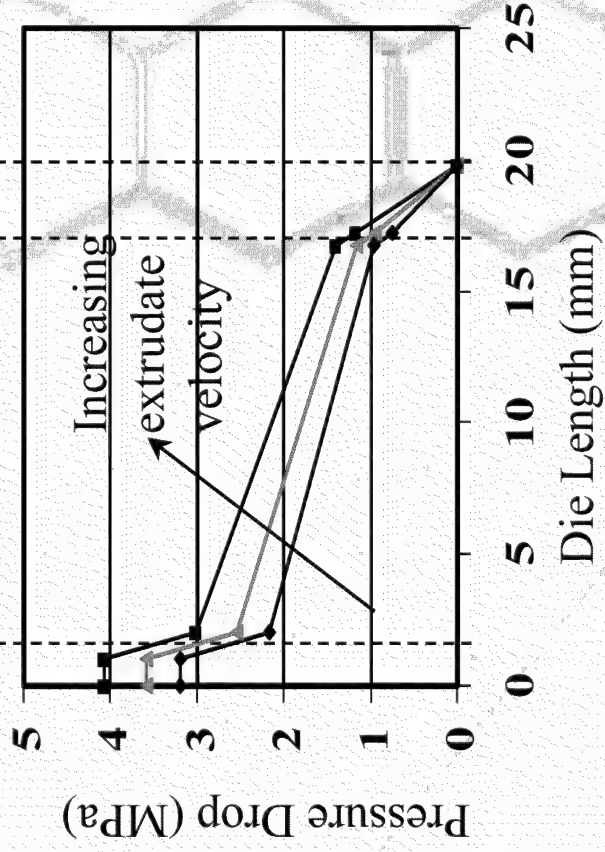
Linear Cellular Die Design

Projected Pressure Drops In Linear Cellular Dies



Planned Work:

- Verify linear cell die pressure drop model by:
 - Measuring pressure vs. die length
 - Measuring pressure vs. web thickness



Paste parameters:

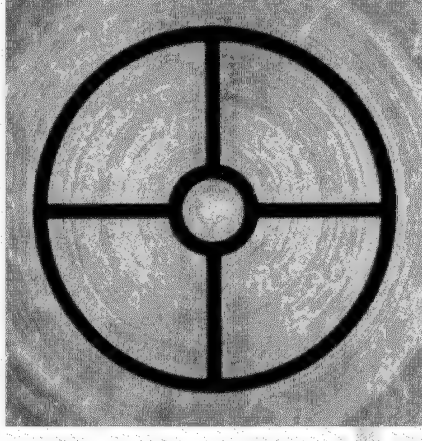
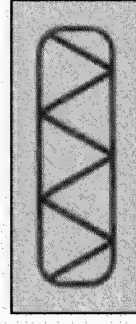
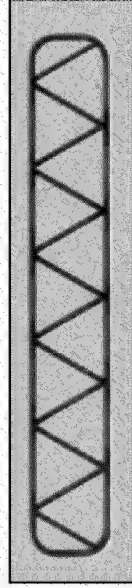
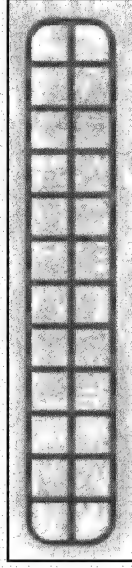
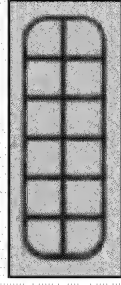
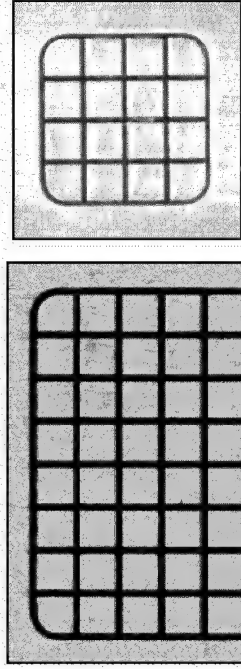
$$\sigma_o = 0.3317 \text{ MPa}$$

$$\tau_o = 0.0306 \text{ MPa}$$

$$\alpha = 0.00265 \text{ MPa-s/mm}$$

$$\beta = 0.0009 \text{ MPa-s/mm}$$

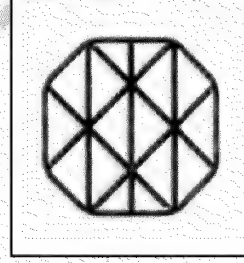
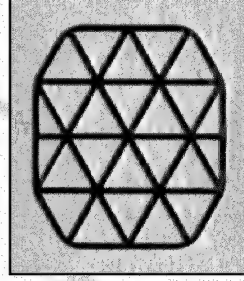
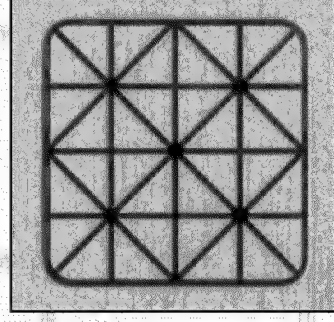
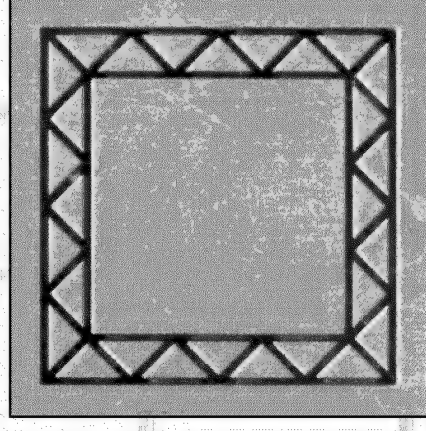
Linear Cell Extrusion Dies Designed at Georgia Tech



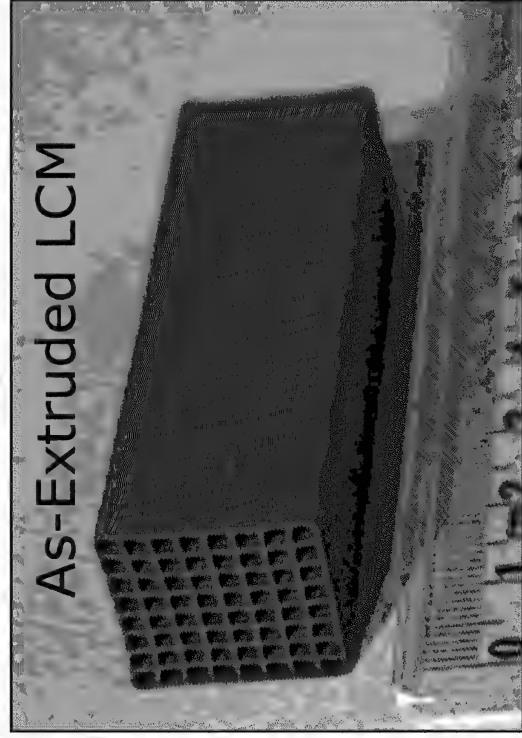
Cell Size = 2.5 mm
for Square Cells

All Die Sizes Are Proportional

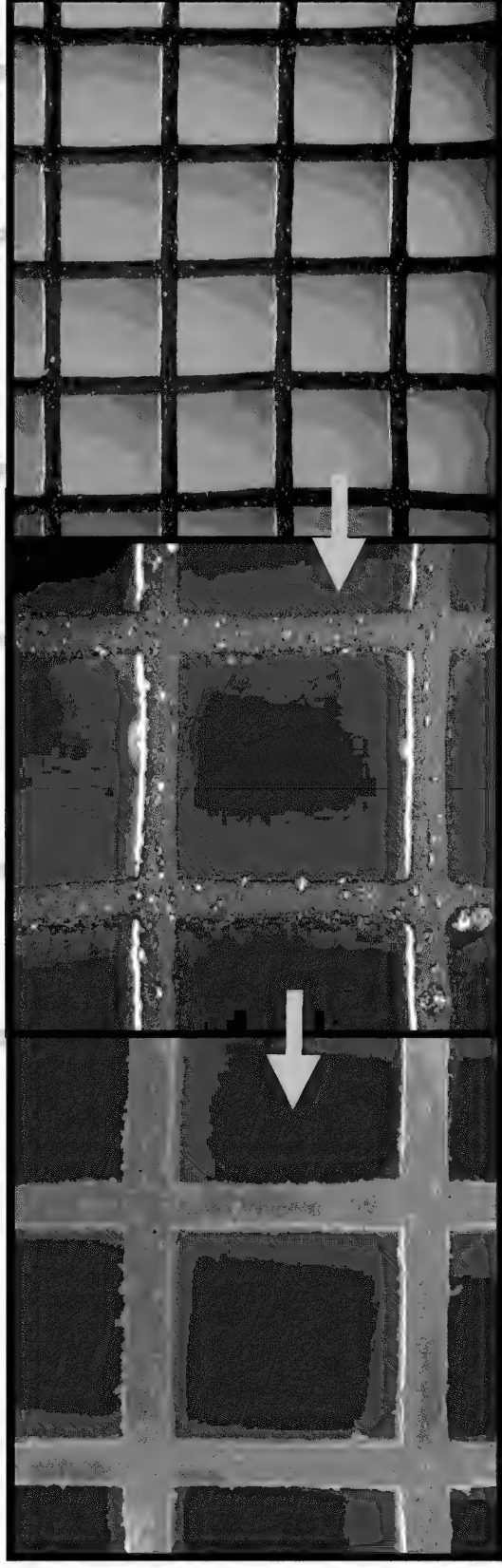
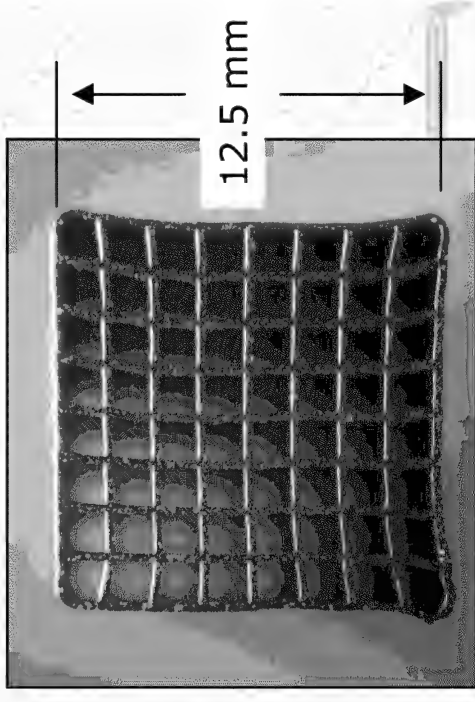
20 mm



Square Cell, 8X8, Maraging Steel LCM



Reduction
& Sintering



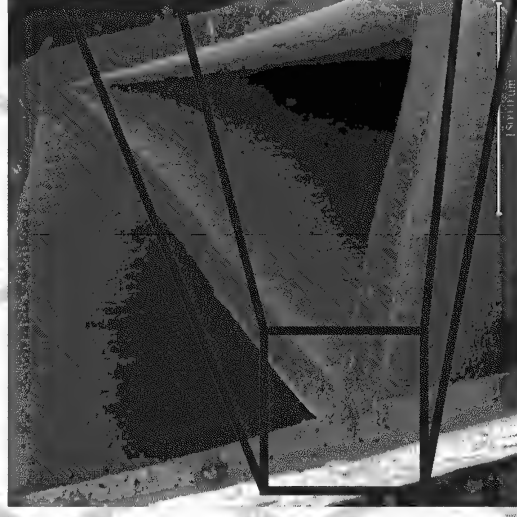
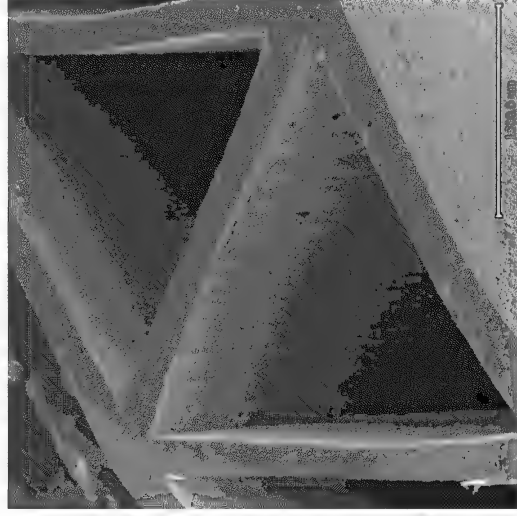
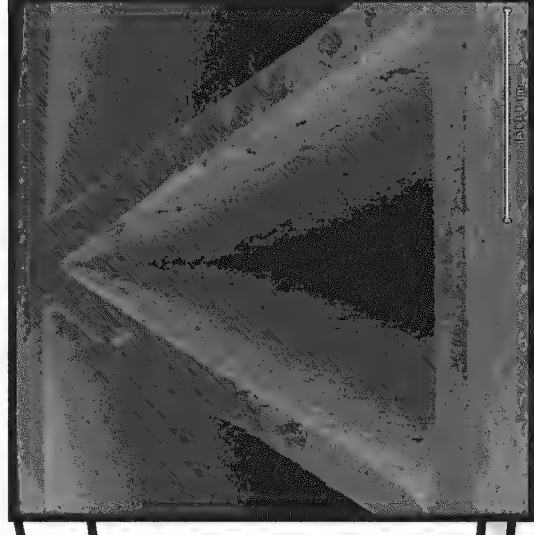
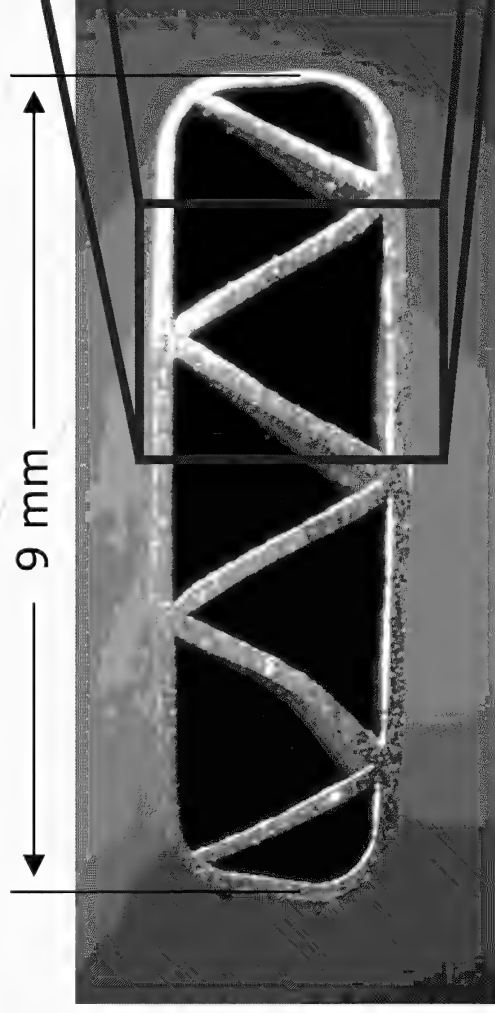
SEM Micrograph

Front Lighting

Back Lighting

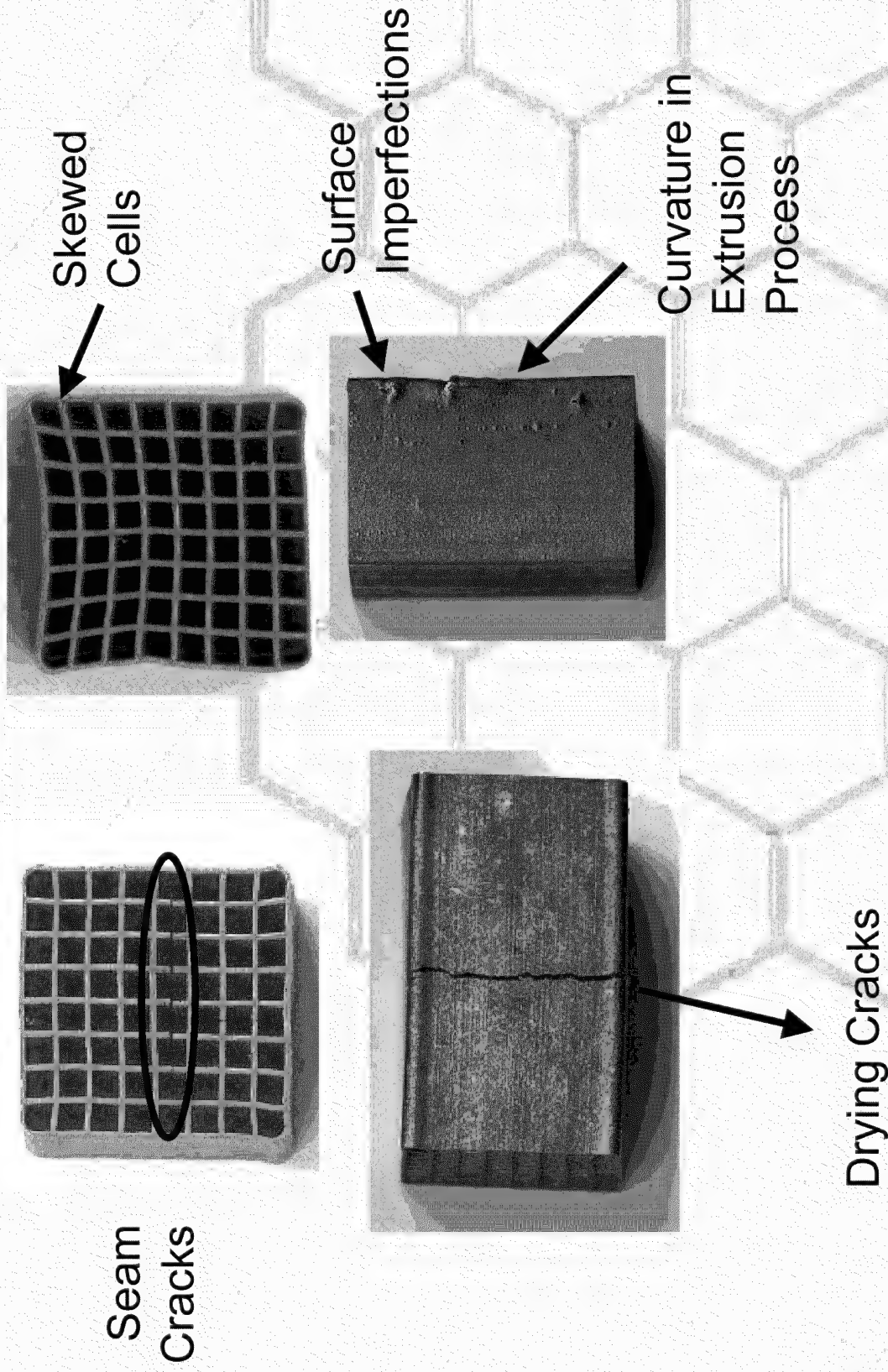
Triangular Cell Extrusions

Maraging 200

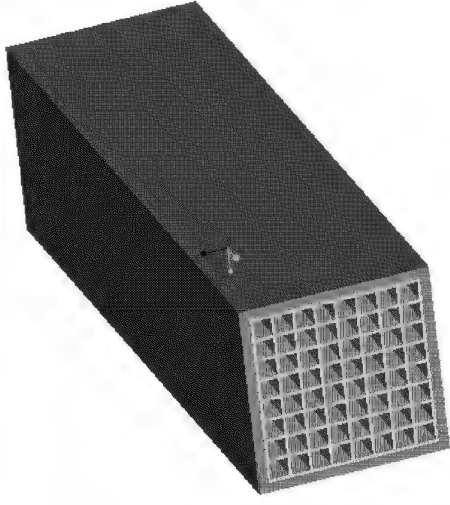


Compression Behavior of LCAs

LCA Specimen Defects

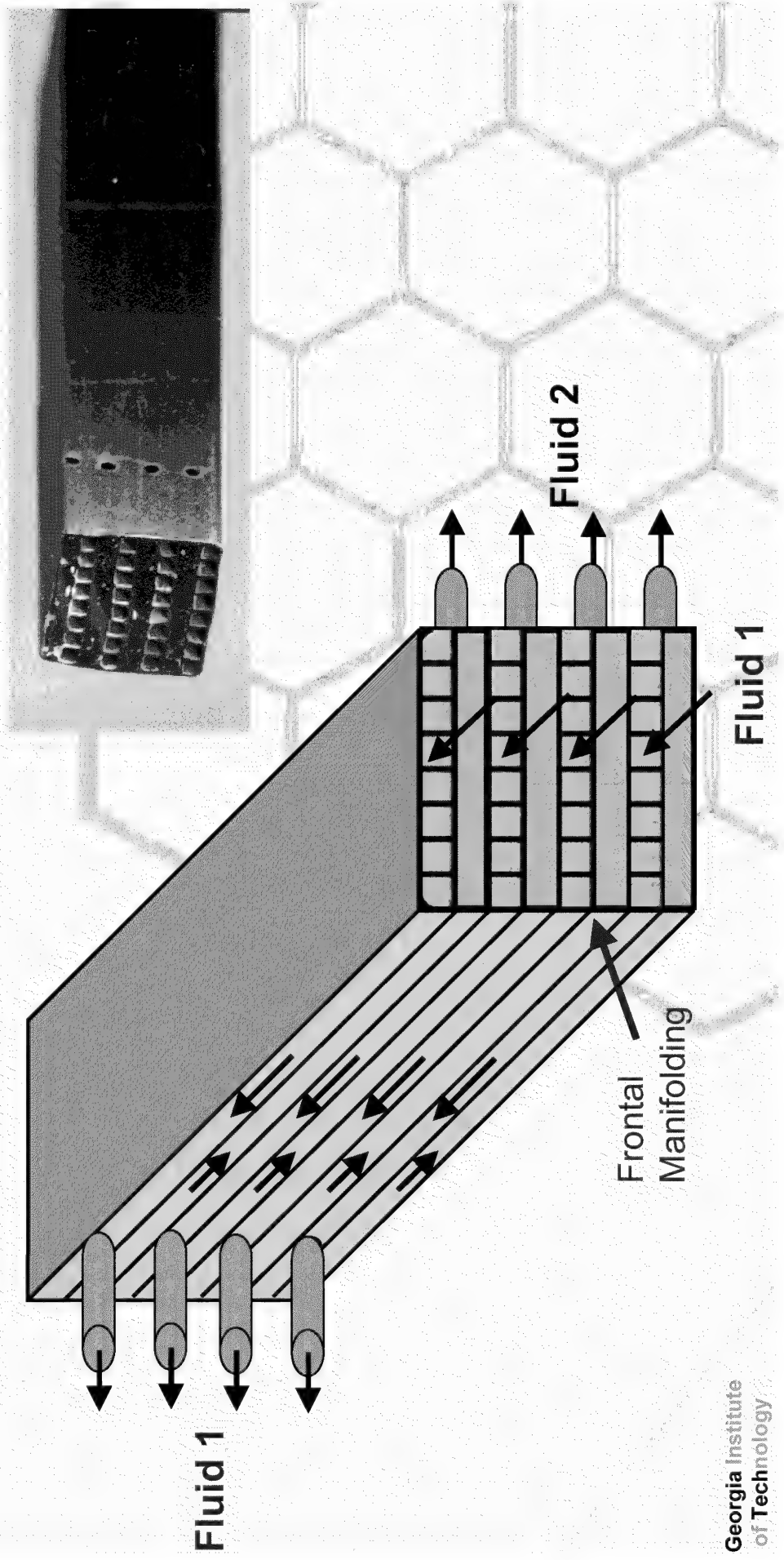


LCMs as Heat Exchangers

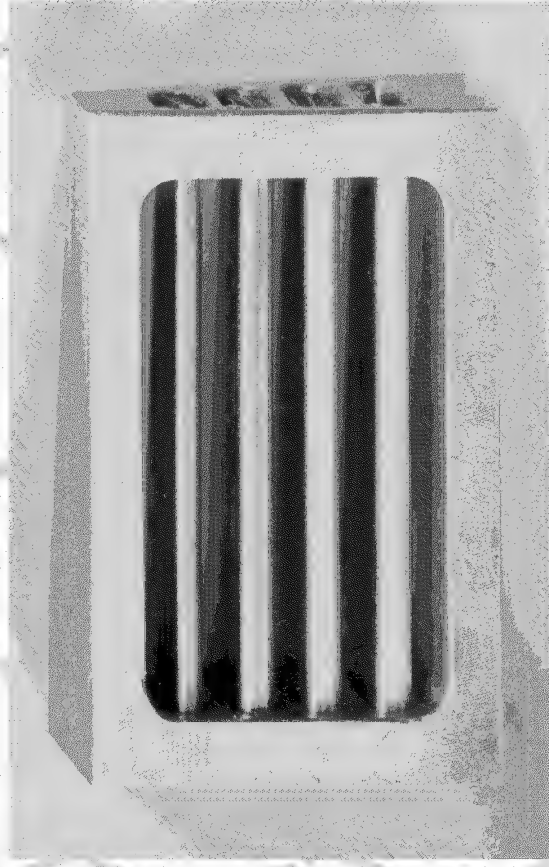
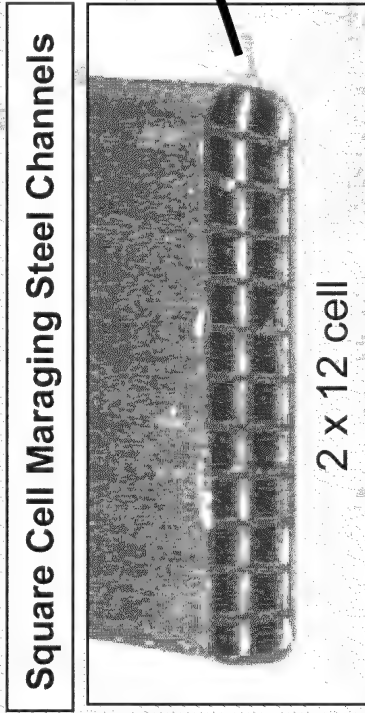
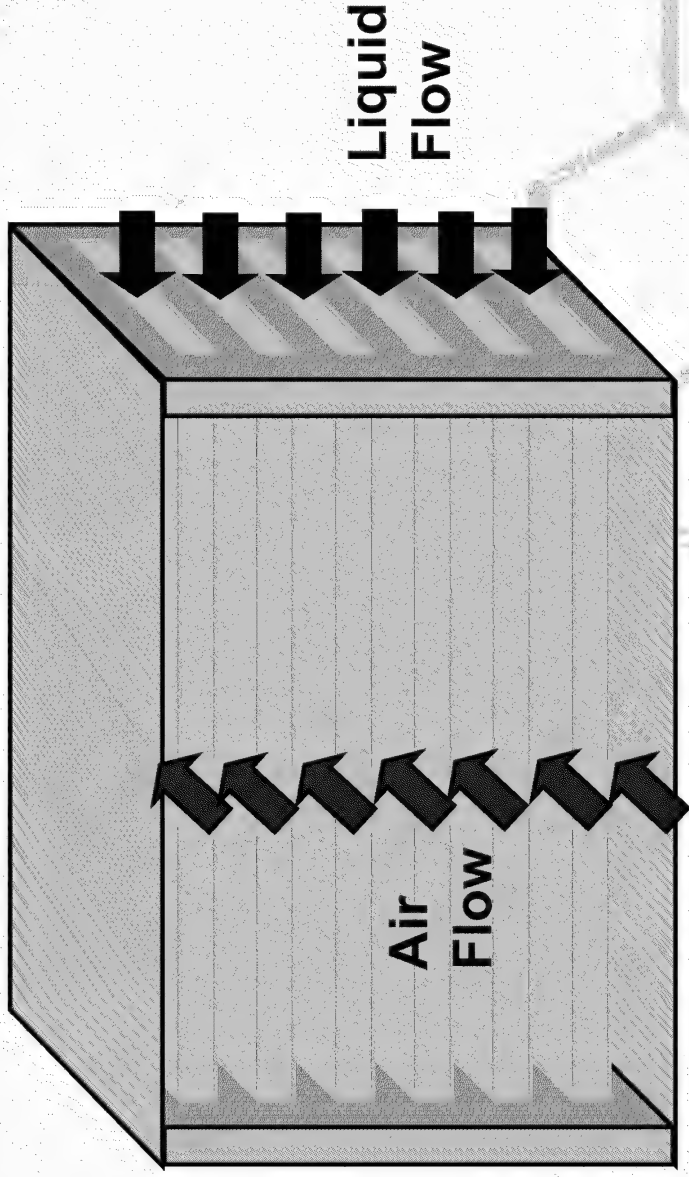


Counter Current Heat Exchanger

Counter current flow of two fluids on alternating rows is easily manifolder. When alternate rows of cells are plugged at one end and connecting holes are drilled in the same cells at the opposite end, flow paths are provided for fluid 1 on alternating rows. The opposite flow pattern is provided for fluid 2 by plugging opposite rows on the other end and drilling exit holes near the front face. This permits easily fabricated frontal manifolding for flow control.



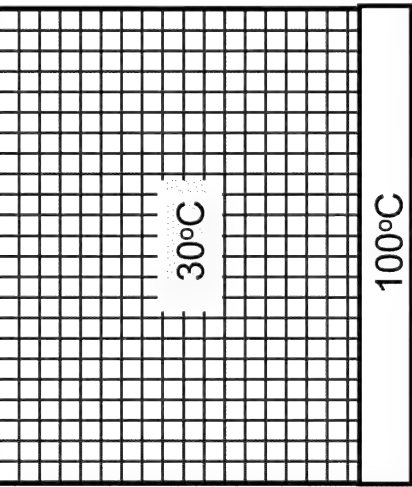
Northrop Grumman Prototype Heat Exchanger for Electronic Cooling



Forced Air CPU Cooling - Design

Conditions:

- 50 X 64 mm inlet, 79 mm length
- Input Air = 30°C, Spreader = 100°C
- Max pressure Drop = 0.06 in. H₂O
- Max Air Flow = 12 CFM
- Cell Wall Conductivity = 165 W/m-K



Ideal Isothermal
Q(W), 365
R(°C/W), 0.19
J(W/cm²), 92
T = 78 μm
C = 2.6 mm

Proprietary

Q(W), 286-317
R(°C/W), 0.24-0.22
J(W/cm²), 72-79
T = 440 μm
C = 4.0 mm

Proprietary

Q(W), 306-340
R(°C/W), 0.23-0.21
J(W/cm²), 79-72
T = 272 μm
C = 3.4 mm

Proprietary

Q(W), 324-350
R(°C/W), 0.22-0.20
J(W/cm²), 81-88
T = 204 μm
C = 3.4 mm

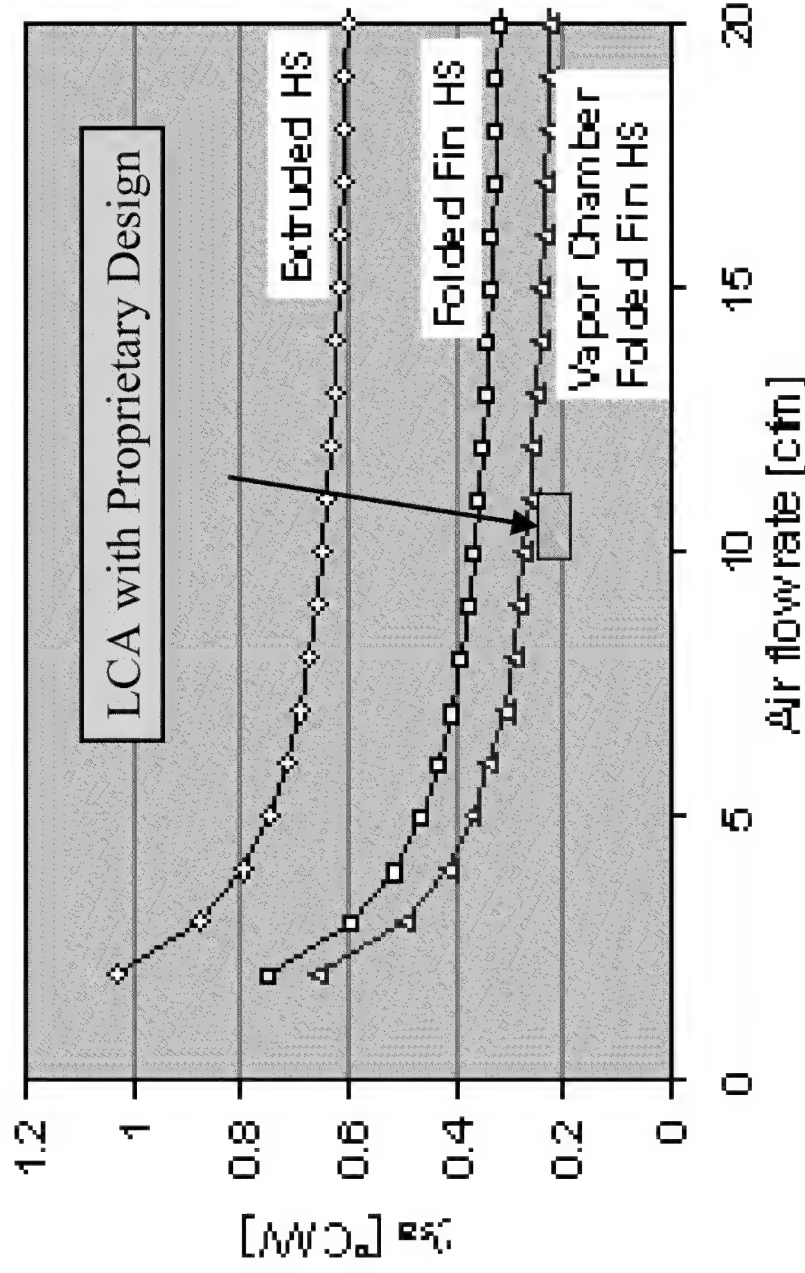
Proprietary

Q(W), 332-354
R(°C/W), 0.21-0.20
J(W/cm²), 83-89
T = 170 μm
C = 3.4 mm

Lower bound solution for optimized LCA geometry / Upper bound isothermal solution

Forced Air CPU Cooling

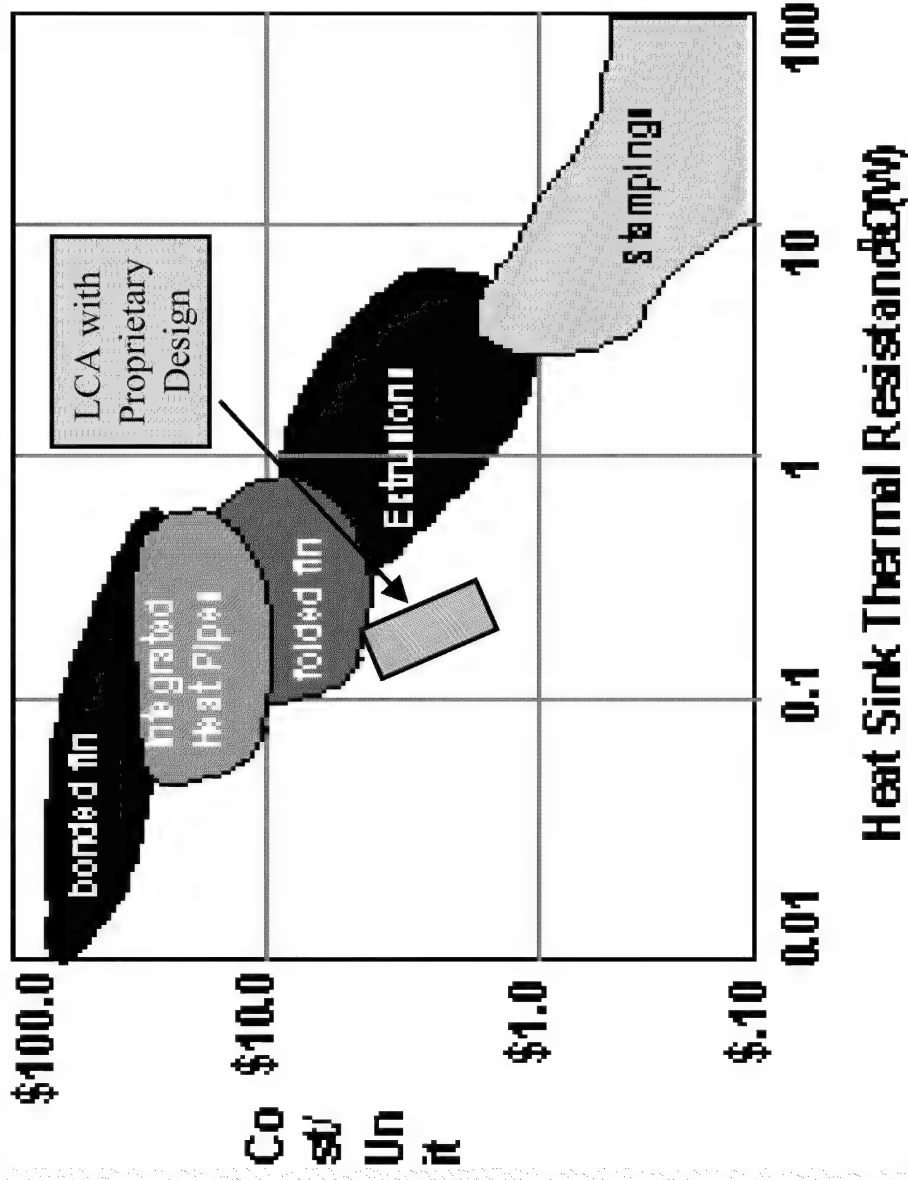
Comparison of Thermal Cooling Solutions: Thermal Resistance vs. Flow Rate



Original Source of Chart:
"Thermal Performance Challenges from Silicon to Systems",
R. Viswanath et al., Intel Technology Journal, 3Q 2000

Forced Air CPU Cooling

Comparison of Thermal Cooling Solutions:
Unit Cost vs. Thermal Resistance



Original Source of Chart:

"Thermal Performance Challenges from Silicon to Systems",

R. Viswanath et al., Intel Technology Journal, 3Q 2000

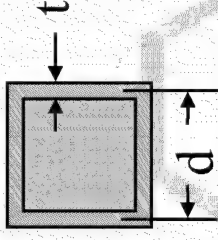
Basic Issues - Heat Sinks

$$\alpha = \frac{\text{total surface area}}{\text{total volume}}$$

Simple for LCAs, controlled by die design, paste rheology, and processing limitations

e.g., square cells $\rightarrow \alpha \approx \frac{4}{d}$

for small t/d .



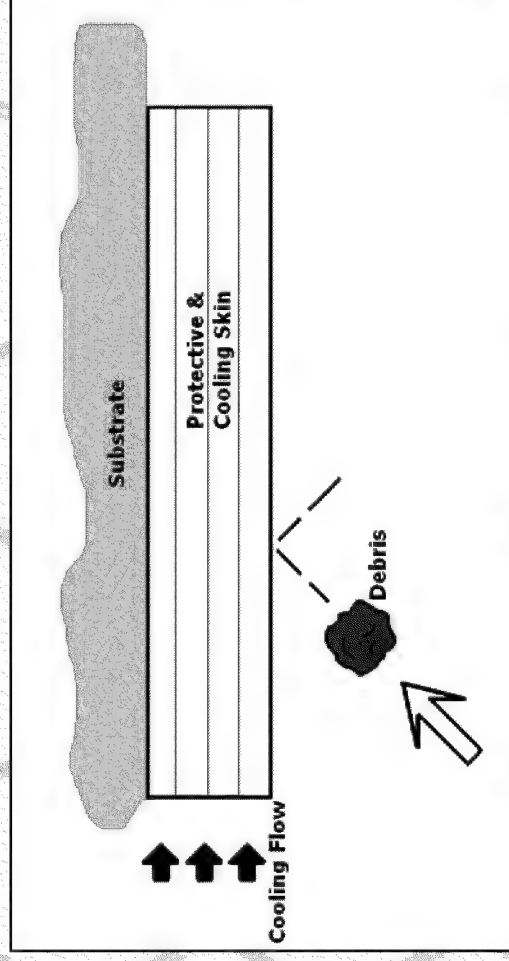
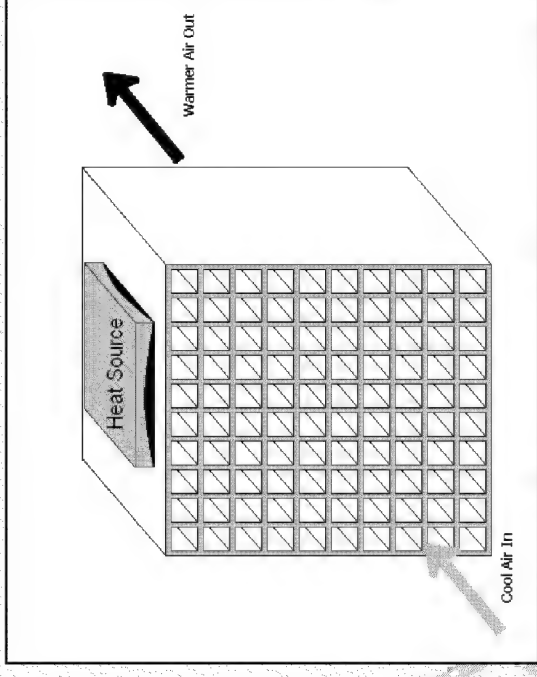
$$\frac{\rho}{\rho_s} = \frac{2t}{d} - \left(\frac{t}{d}\right)^2 \approx \frac{2t}{d} \quad \text{For low density}$$

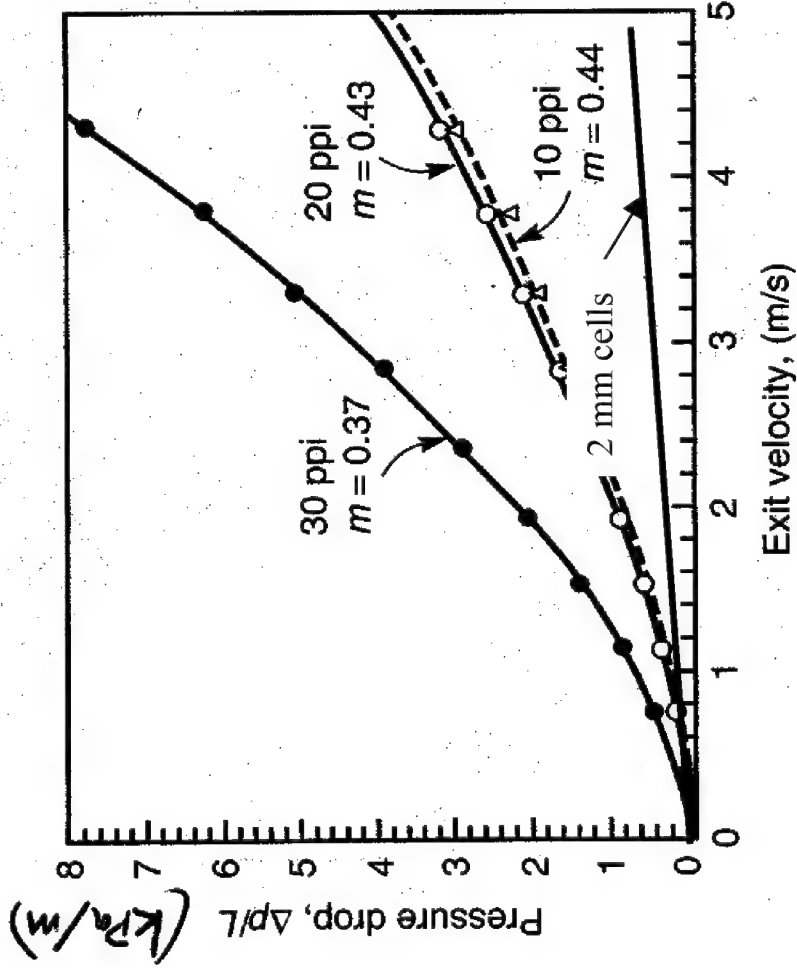
α values are much higher for same characteristic dimension of LCAs than for open cell foams

- Laminar (or transition) flow dominates for air cooling; simple pipe friction & heat transfer coefficient relations exist. Note: in porous media, transition occurs at Re in the 100-300 range - but this is not a classical random porous medium
- Can heat sink dissipate 50-100 W/cm²?
- Strategies: (a) thermal gradients, (b) cell morphology, (c) hybrid heat sinks

Some Applications

- Heat Removal
 - Computer chips
- Recapture of Lost Heat
 - Engines
- Structural / Heat Transfer
 - Actively cooled skins





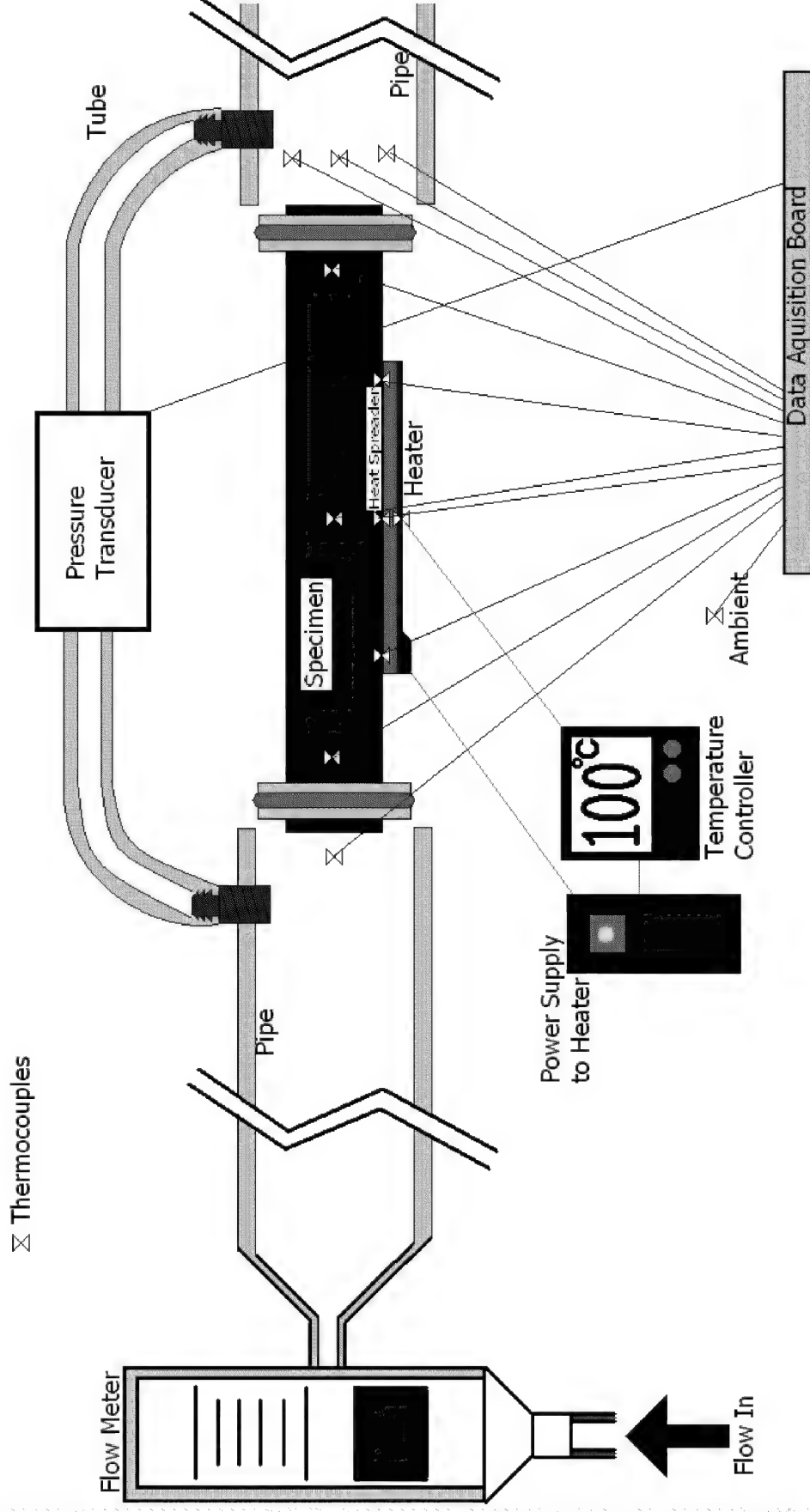
Laminar Flow Pressure Drop

$$\frac{\Delta P}{\rho g} = f \frac{L}{d} \frac{V^2}{2g}, \quad \text{Re} = \frac{\rho V d}{\mu} \quad (\text{general relation})$$

$$\frac{\Delta P}{\rho g} = f \frac{L}{d} \frac{V^2}{2g} = \frac{57}{\text{Re}} \frac{L}{d} \frac{V^2}{2g}, \quad \rightarrow \Delta P = \frac{28.5 \mu L V}{d^2}$$

laminar flow in square duct

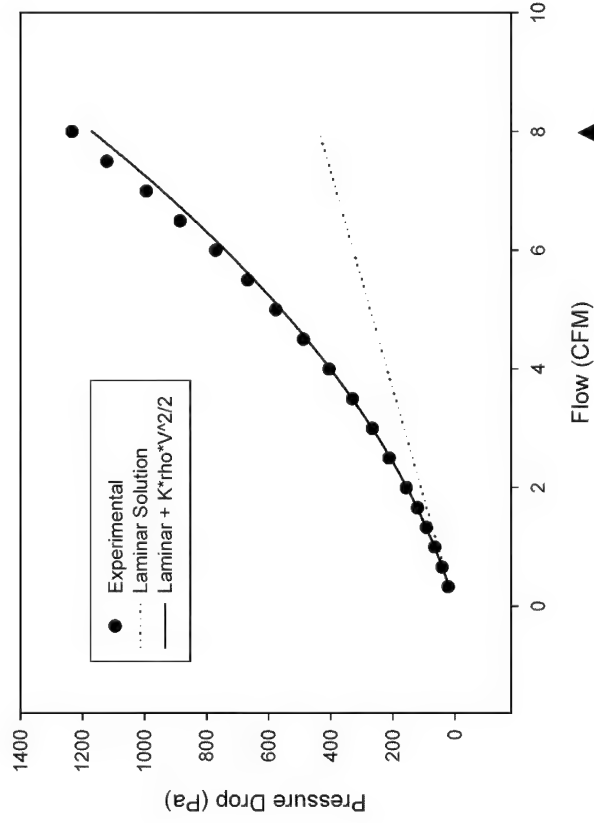
Experimental Apparatus



Pressure Drop vs. Flow and Head Loss

8x8 Maraging Steel LCA

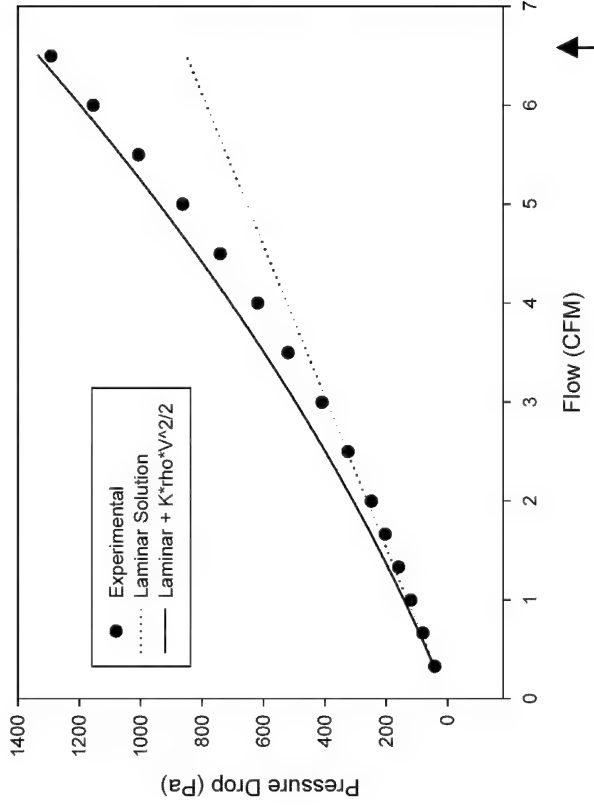
Length = 4.36 cm, d = 1.35 mm, t = 0.23 mm
K = 1.2



Pressure Drop vs. Flow and Head Loss

8x8 Maraging Steel LCA

Length = 11.2 cm, d = 1.37 mm, t = 0.25 mm
K = 1.2



$$\Delta P_{LCA} = \Delta P|_{\text{laminar duct}} + K \frac{\rho V^2}{2} = \Delta P|_{\text{load}}$$

Experiments: LCM Conductivity

<u>Composition (LCM)</u>	<u>Conductivity (W/m·K)</u>
• CuNi 8% 64.48
• CuNi 3% 130.31
• Cu 165.52
• CuAg 1% 192.27
• CuAg 3% 248.00

Tabular Values (Incropera & Dewitt, 1996)

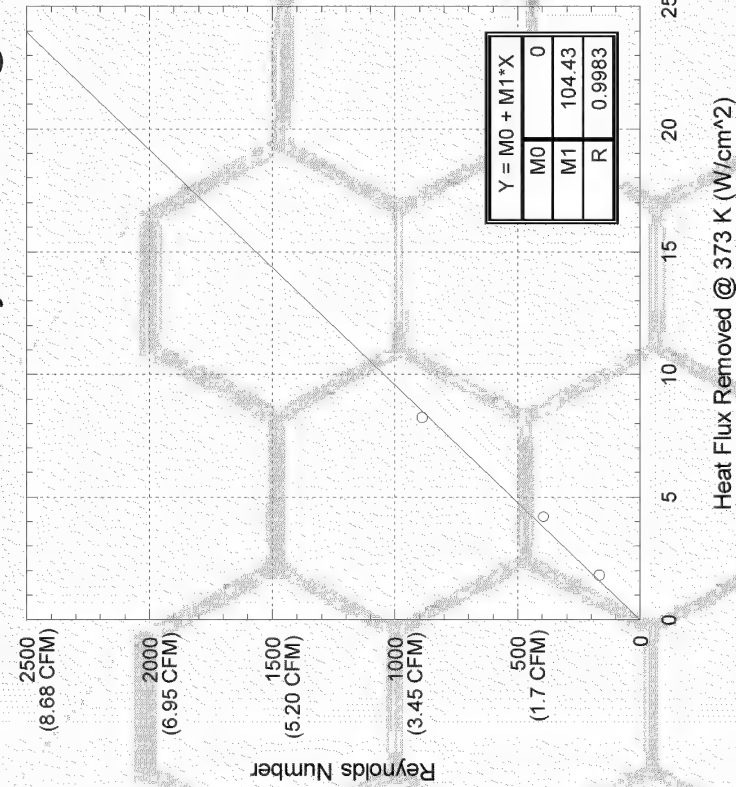
• Pure Copper 401
• Commercial Bronze(90% Cu, 10% Al) 52
• Constantan(55% Cu, 45% Ni) 23

Experimental Results: 2" heated length

8x8 Copper
with heater
at 373 K

○ Reynolds Number

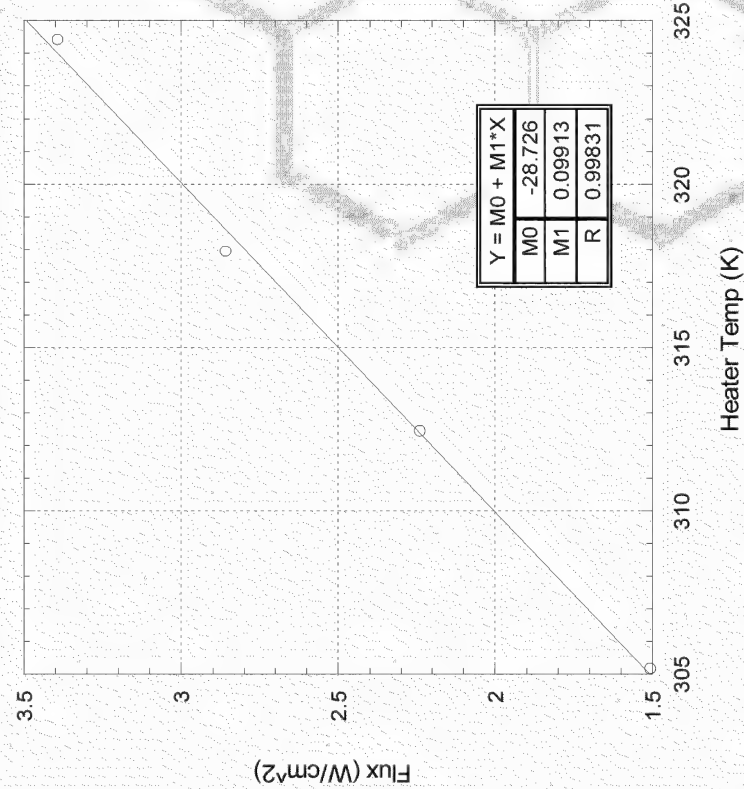
Heat Flux Removed vs. Reynolds Number @ 373 K



8x8 Copper
with 8% Nickel

○ Flux (W/cm²)

Heat Flux Removed vs. Temp @ Re# 890



Interpolation shows Flux =
8.25 W/cm² at 373 K

Upper and Lower Bound Solutions on Steady State Heat Transfer Rates for Square Cell LCMs

Upper:

$$q^{\text{isothermal}} = \rho C_p N d^2 V (T_b - T_\infty) \{1 - \exp(-\beta)\}$$

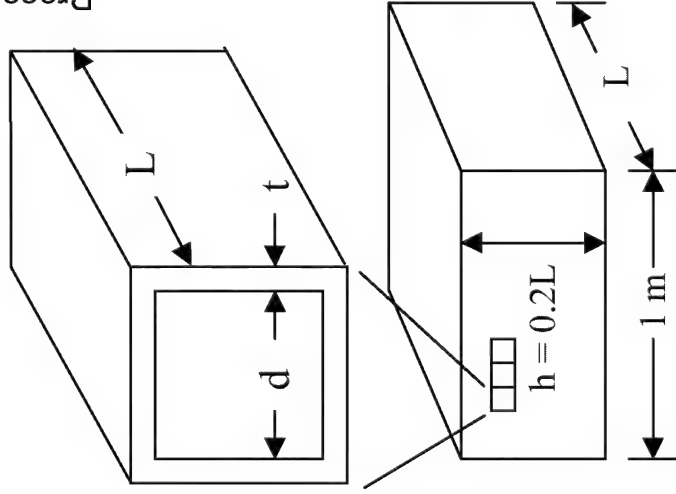
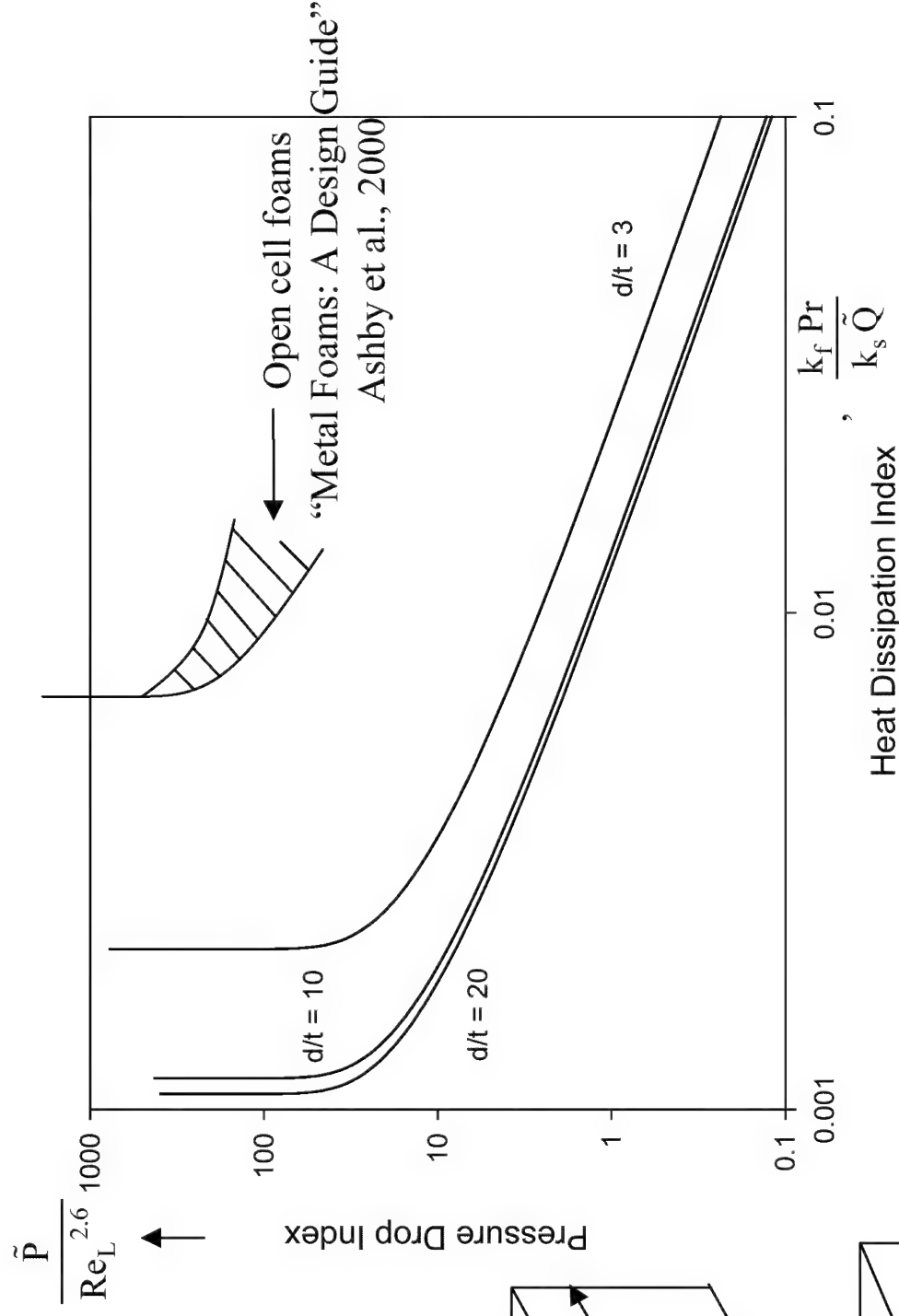
Lower:

$$q^{\text{peripheral}} = \rho C_p N d^2 V (T_b - T_\infty) \{1 - \exp(-\beta)\} \sqrt{\frac{4}{\text{LCM}}} \tanh \left\{ \sqrt{\frac{\text{LCM}}{4}} \right\}$$

$$q^{\text{base}} = \rho C_p N d^2 V (T_b - T_\infty) \{1 - \exp(-\beta)\} \sqrt{\frac{1}{4 \text{LCM}}} \tanh \left\{ \sqrt{4 \text{LCM}} \right\}$$

$$\tilde{P} = \frac{\Delta P V h L^2}{\rho v^3}$$

$$Re_L = 5000 = \frac{\rho V L}{\mu} \quad \left(Re_d = \frac{\rho V d}{\mu}, \quad d \ll L \right) \quad \tilde{Q} = \frac{\rho C_p N d^2 V (T_b - T_\infty)}{k_s (T_b - T_\infty)} \left\{ 1 - \exp \left(- \frac{4 Nu k_f L}{\rho d^2 V C_p} \right) \right\}$$



Comparison to Open Cell Metal Foams

Entry Length Effects for Square Cell LCMS

$$h = \text{Nu} \frac{k_f}{d}$$

$$\text{Nu}_{m,T} = 0.1222 + 2.8337 \ln \left(\frac{1}{x^*} \right) - 0.8083 \left\{ \ln \left(\frac{1}{x^*} \right) \right\}^2 + 0.1134 \left\{ \ln \left(\frac{1}{x^*} \right) \right\}^3 \quad x^* = \frac{x}{d \text{RePr}}$$

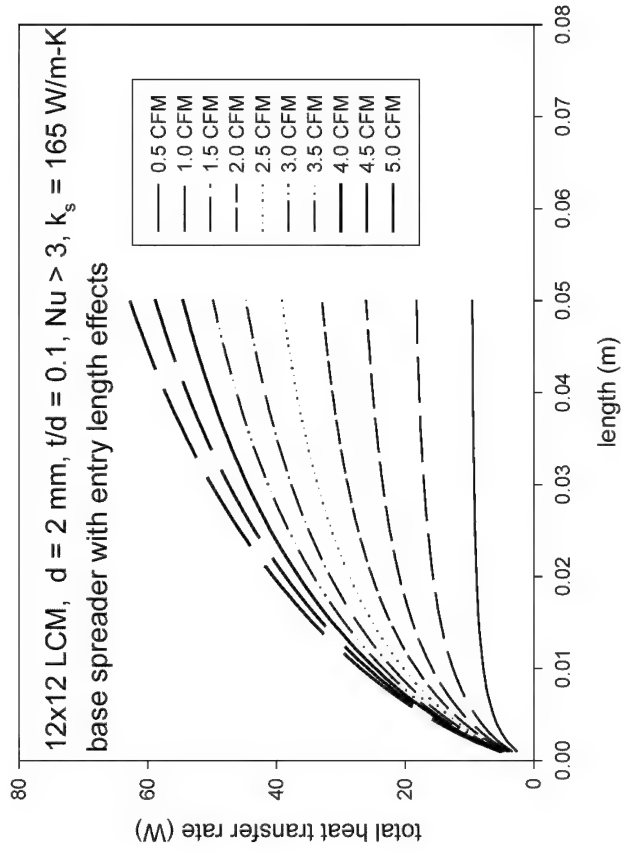
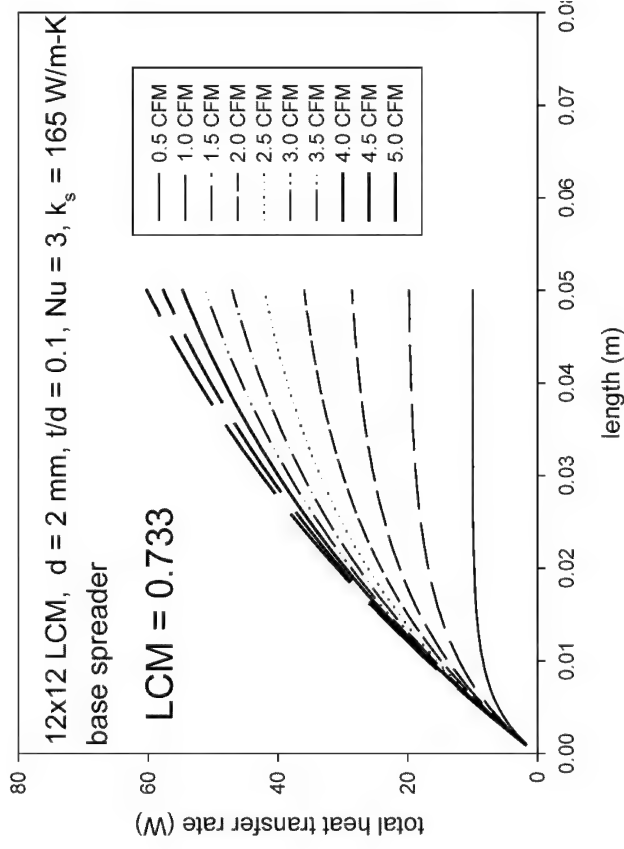
$$\text{Nu}_{\text{ave}} = \frac{1}{L} \int_0^L \text{Nu}_{m,T} dx = 2.0197 - 1.8975 \ln \left(\frac{L}{d \text{RePr}} \right) - 0.4681 \left\{ \ln \left(\frac{L}{d \text{RePr}} \right) \right\}^2 - 0.1134 \left\{ \ln \left(\frac{L}{d \text{RePr}} \right) \right\}^3$$

$$\text{for } \frac{L}{d} \leq 0.21128 \text{ RePr}$$

$$\text{Nu}_{\text{ave}} = 3 + 0.267 \text{ RePr} \frac{d}{L} \quad \text{for } \frac{L}{d} > 0.21128 \text{ RePr}$$

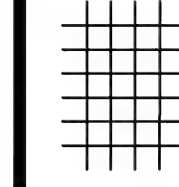
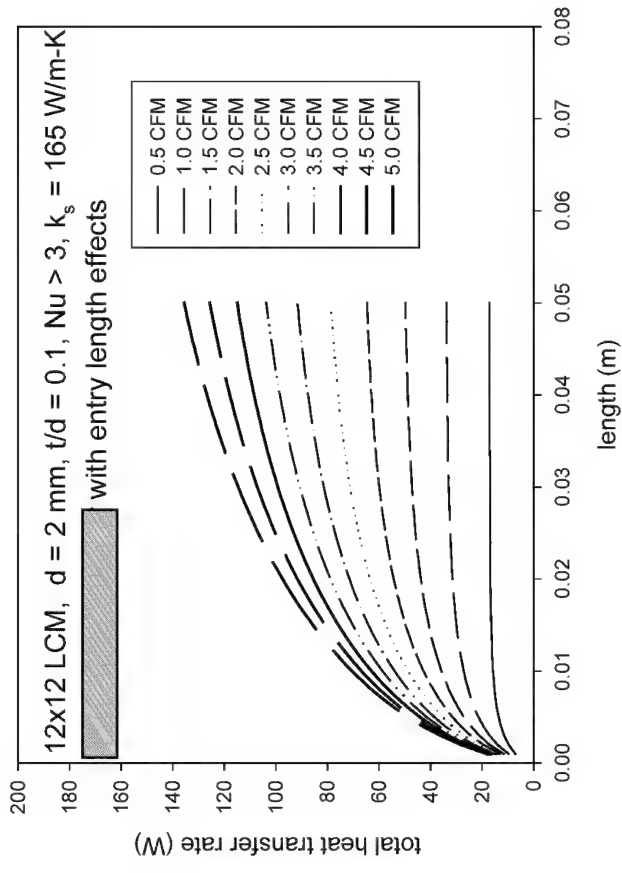
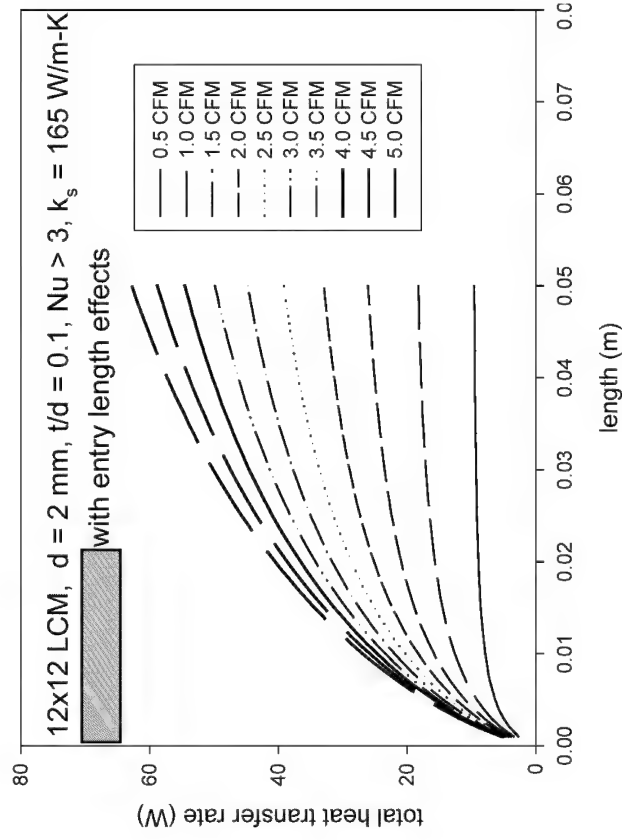
“Advances in Heat Transfer: Laminar Flow Forced Convection in Ducts”
by R.K. Shah and A.L. London, Academic Press, NY, 1978 (pg. 220).

Entry Length Effects for Square Cell LCMs

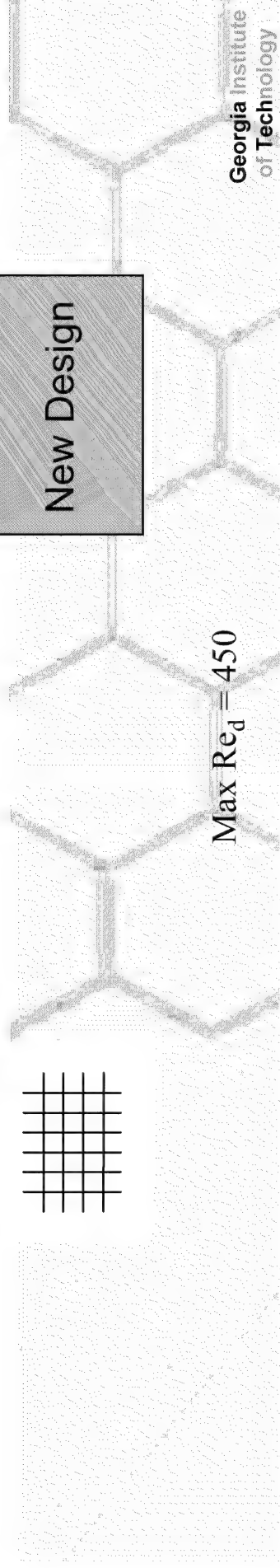


Max $Re_d = 450$

New Design Effects for Square Cell LCMs



New Design



Max $Re_d = 450$

Finite Difference Code

- The following two equations are good for all of the different types of elements

$$- \dot{E}_{\text{in}} - \dot{E}_{\text{out}} + \dot{E}_{\text{generated}} = \dot{E}_{\text{stored}}$$

$$- q_{i-1} + q_{i+1} + q_{j-1} + q_{j+1} + q_{k-1} + q_{k+1} = 0$$

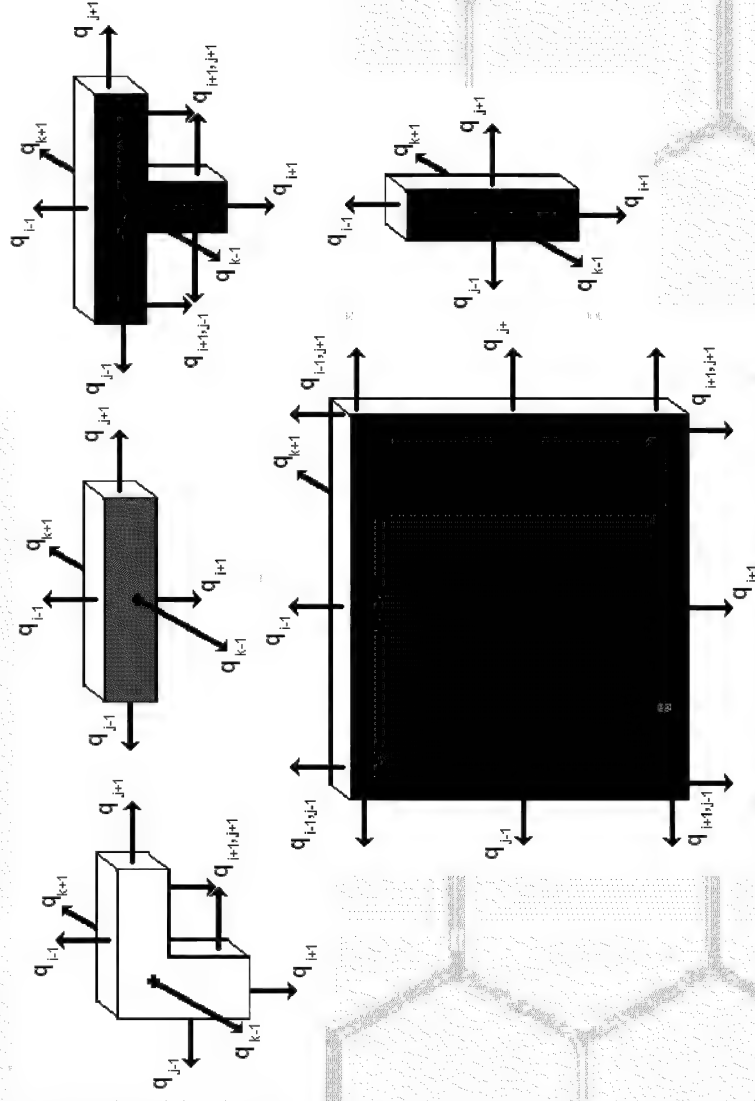
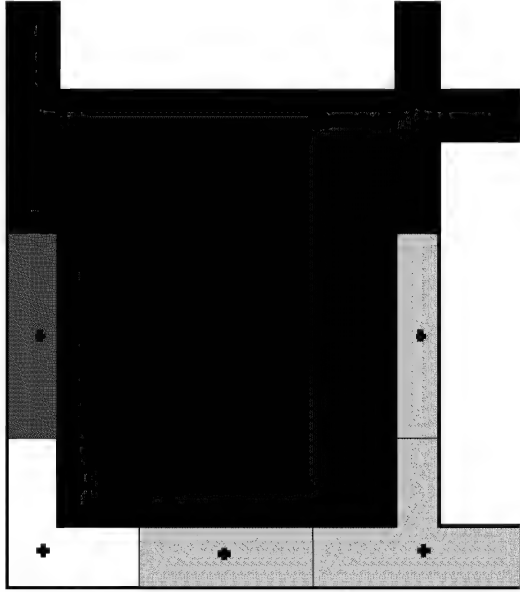
- Each element interacts with the elements around it by one of three methods of heat transfer

$$- Q = m \cdot c_p \cdot (T_{\text{mean,out}} - T_{\text{mean,in}})$$

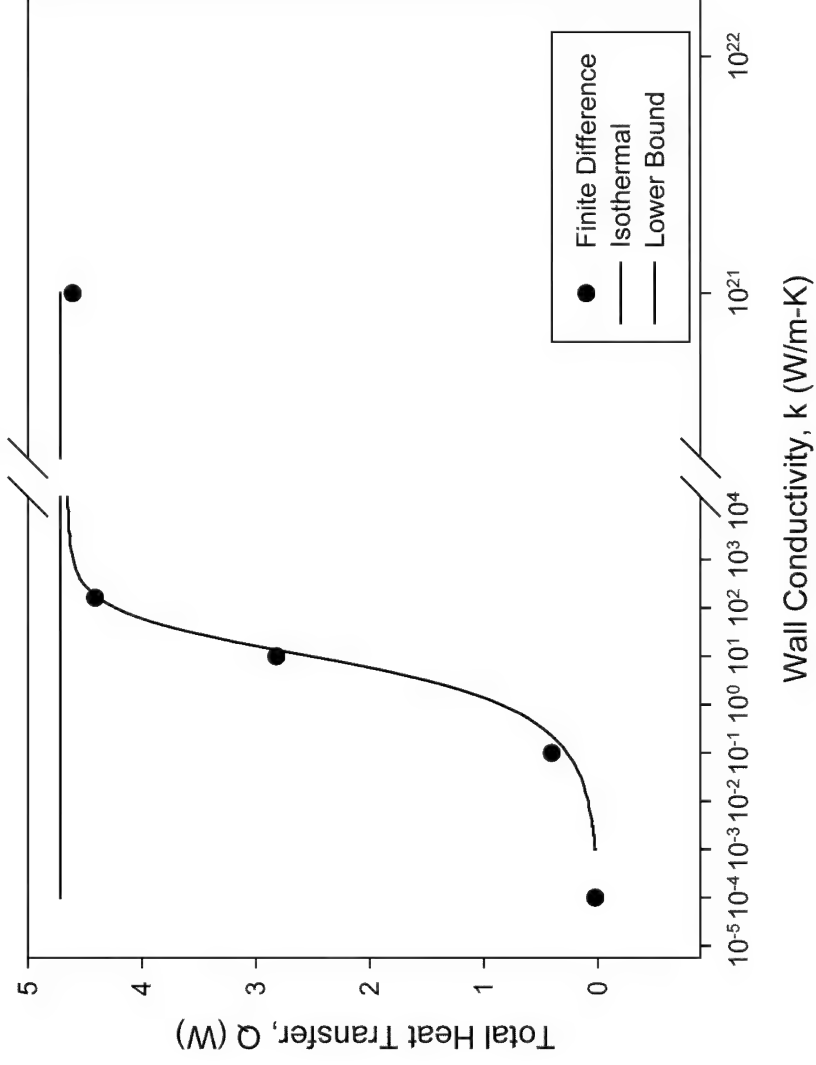
$$- Q = h \cdot A_c \cdot (T_{\text{surface}} - T_{\text{fluid}})$$

$$- Q = -k \cdot A_c \cdot \Delta T / \Delta x$$

Finite Difference Code

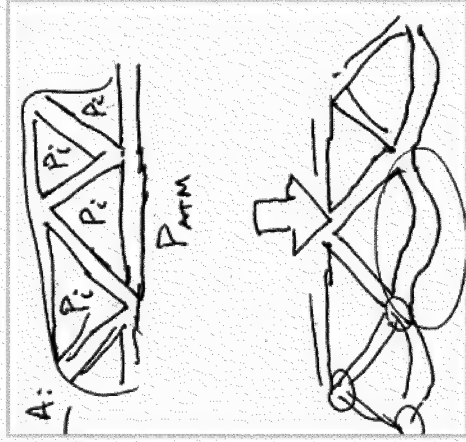


Effect of Conductivity
3x3, d=3mm, t=0.3mm
mass flow/cell = 3.59e-5 kg/s
Constant Temperature One Side
length = 0.02475 m
Nu = 3

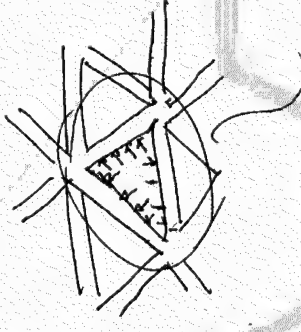


Basic Issues - Heat Sinks

Pressure drop and cell burst overpressure (McDowell, 1999)



$$\frac{P_i}{\sigma_{ys}} = \begin{cases} \frac{16}{9} \left(\frac{\rho}{\rho_s} \right)^2 & \text{for triangular cells} \\ \left(\frac{\rho}{\rho_s} \right)^2 & \text{for square cells} \end{cases}$$

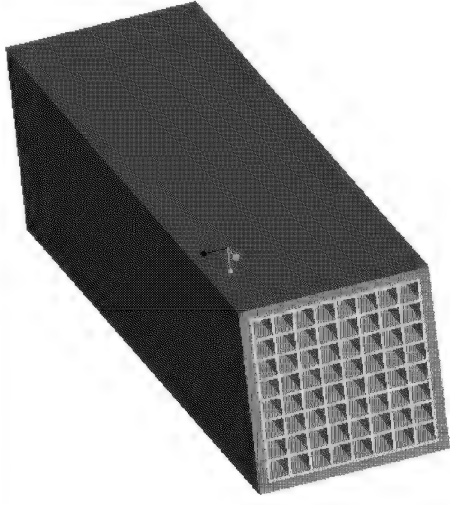


Slightly lower
due to shift of
neutral axis due to
cell wall extension

For a relative density of 10%, P_i is approx. 1% of the plastic flow stress, limited by S_u , i.e.

Al alloys	→	300-500 psi
Ni alloys	→	1000-2000 psi
Cu alloys	→	200-400 psi

LCMs as Structural Materials

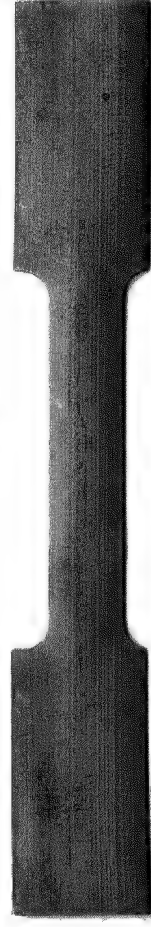
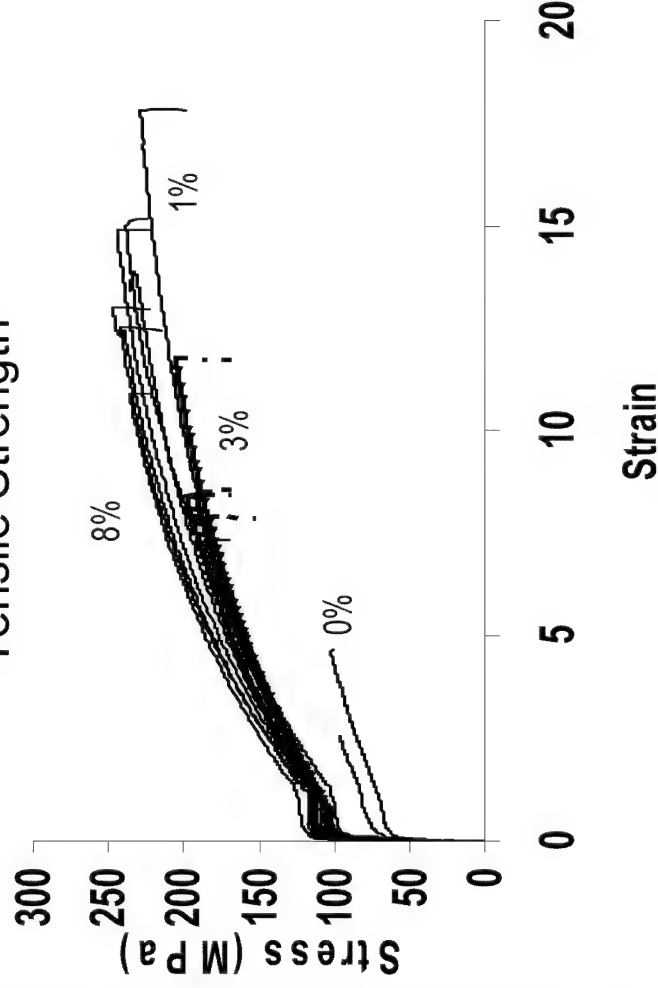


Metallurgical Properties

Copper Alloys

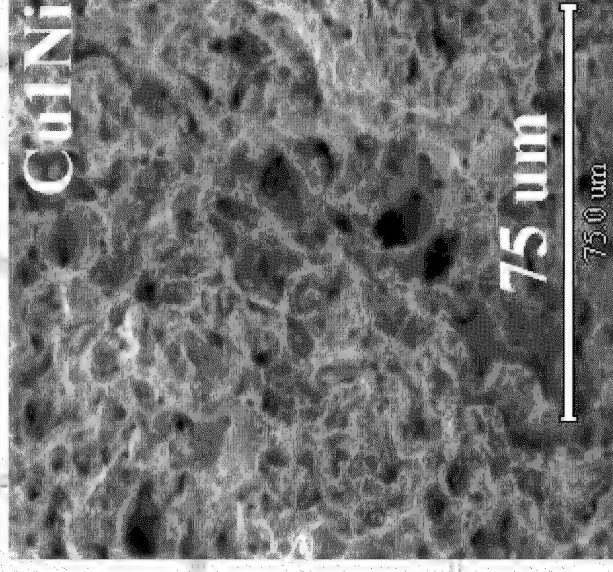
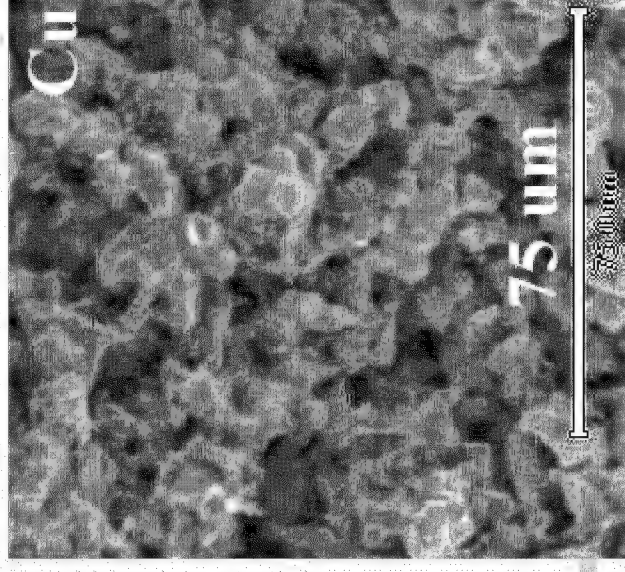
Copper - X%Nickel

Tensile Strength



Thickness = 0.56 mm Width = 5.72 mm

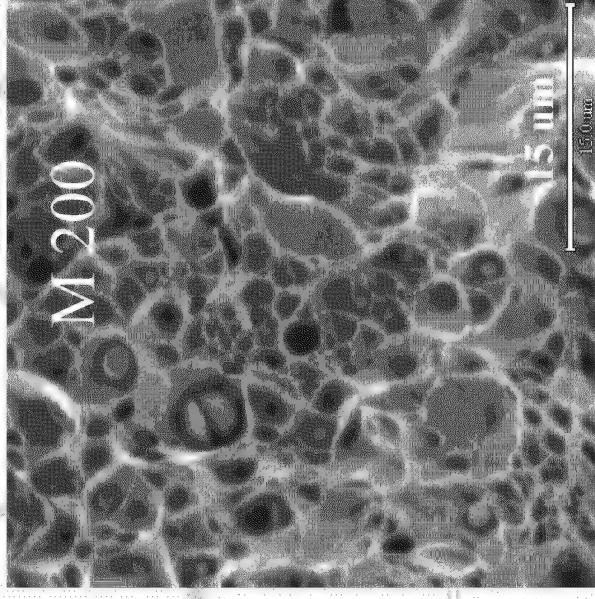
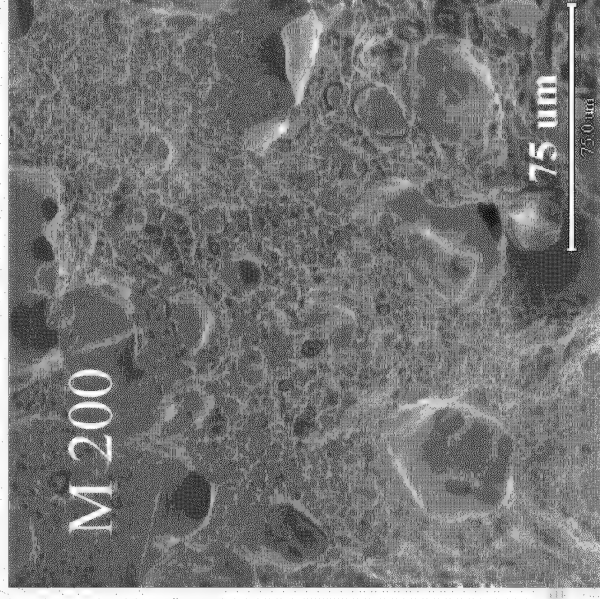
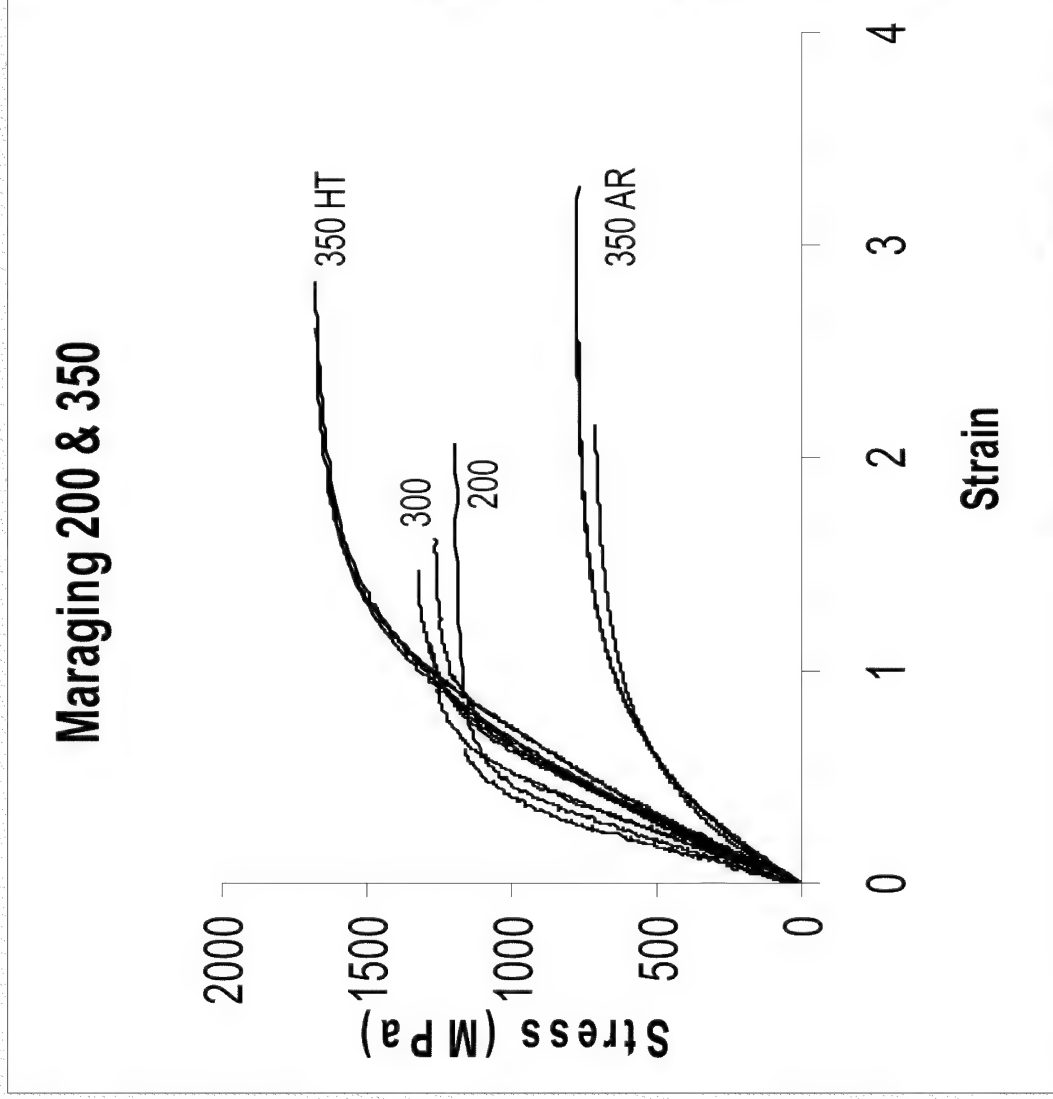
Fracture Surface



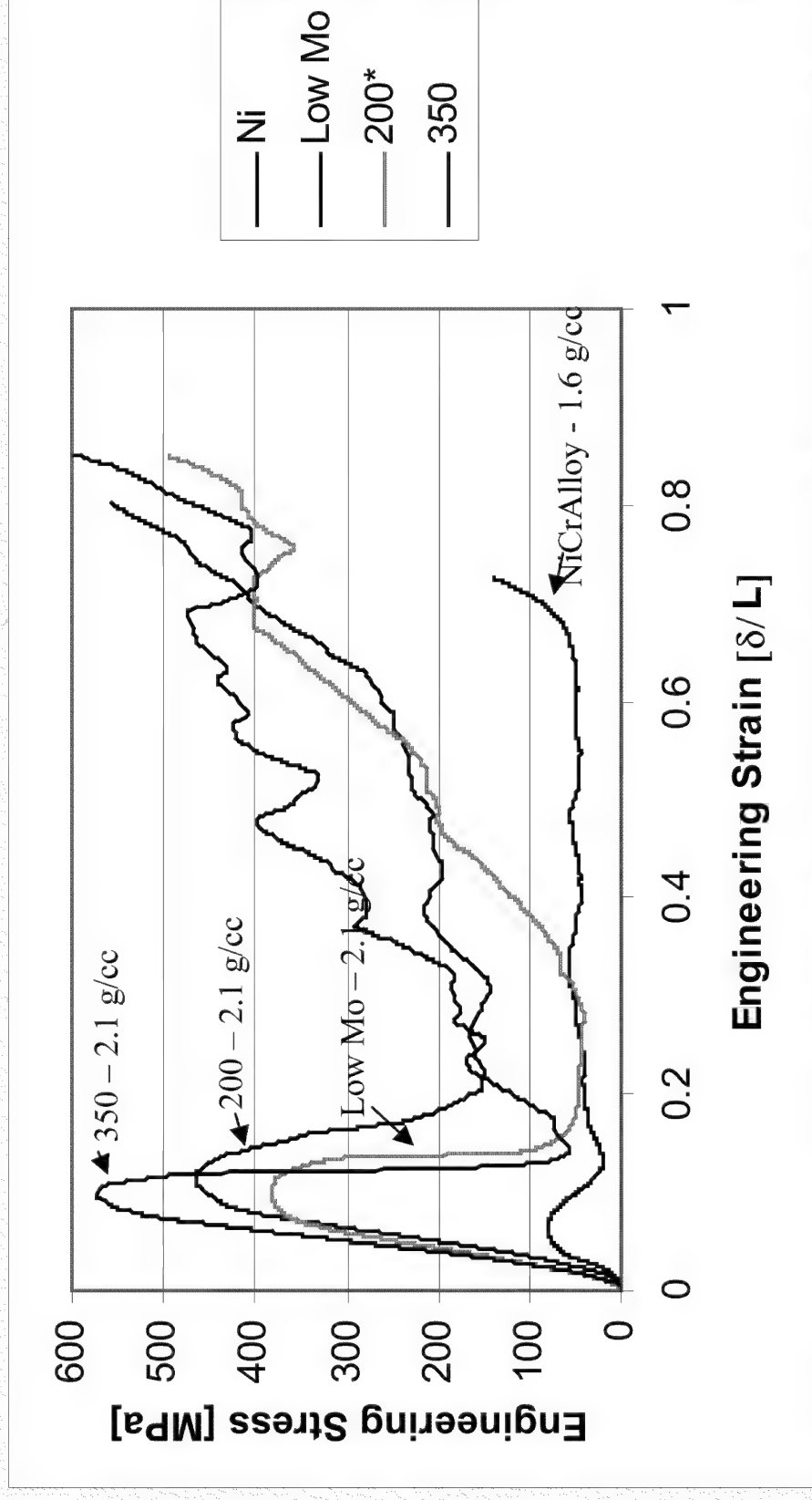
Metallurgical Properties

Maraging Steel

Tensile Strength/ Fracture Surface



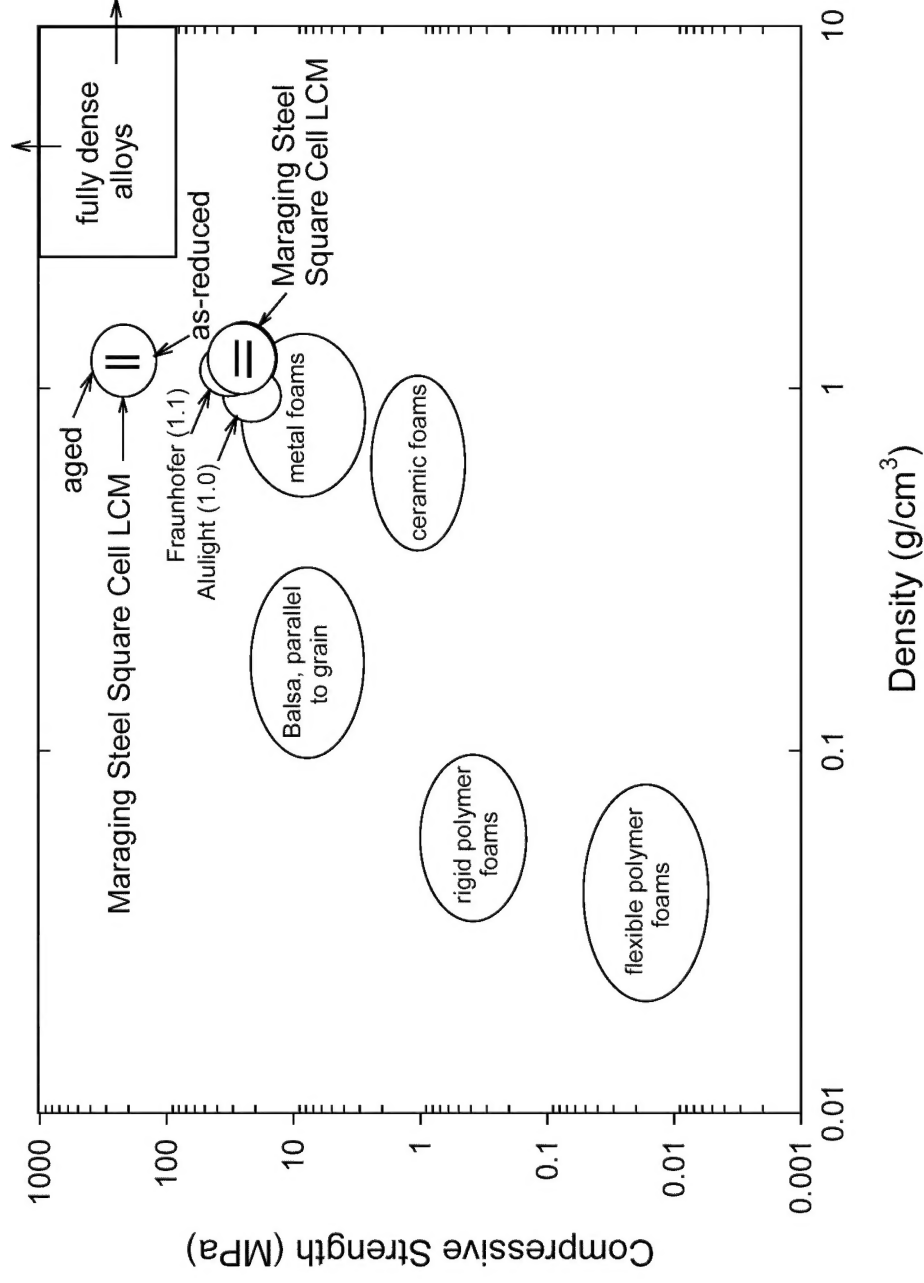
Strength of Square Cell Maraging Steel LCM Loaded Parallel to Axis



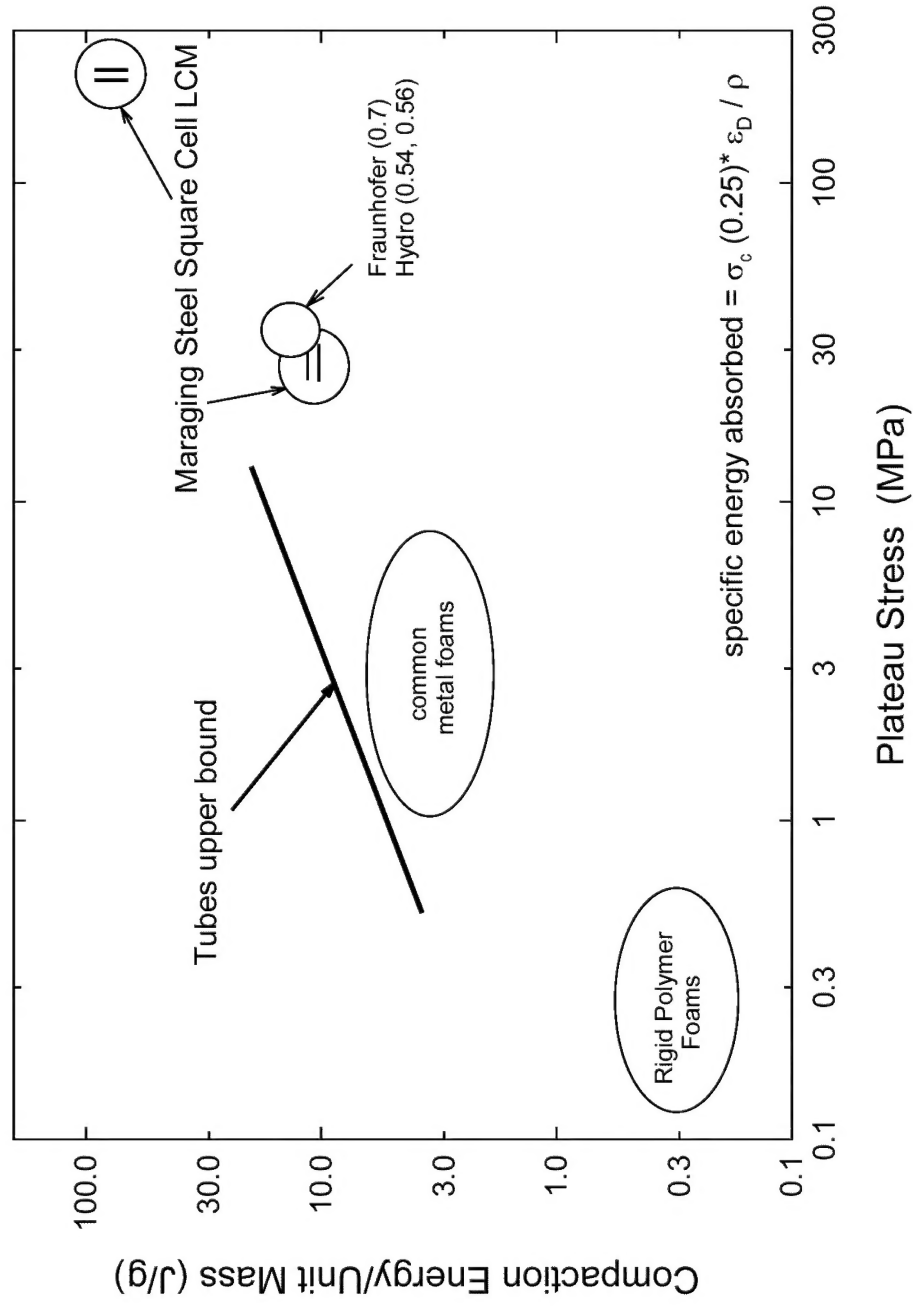
* = Larger Cell Array (8x8)

Low Mo w/ HT2

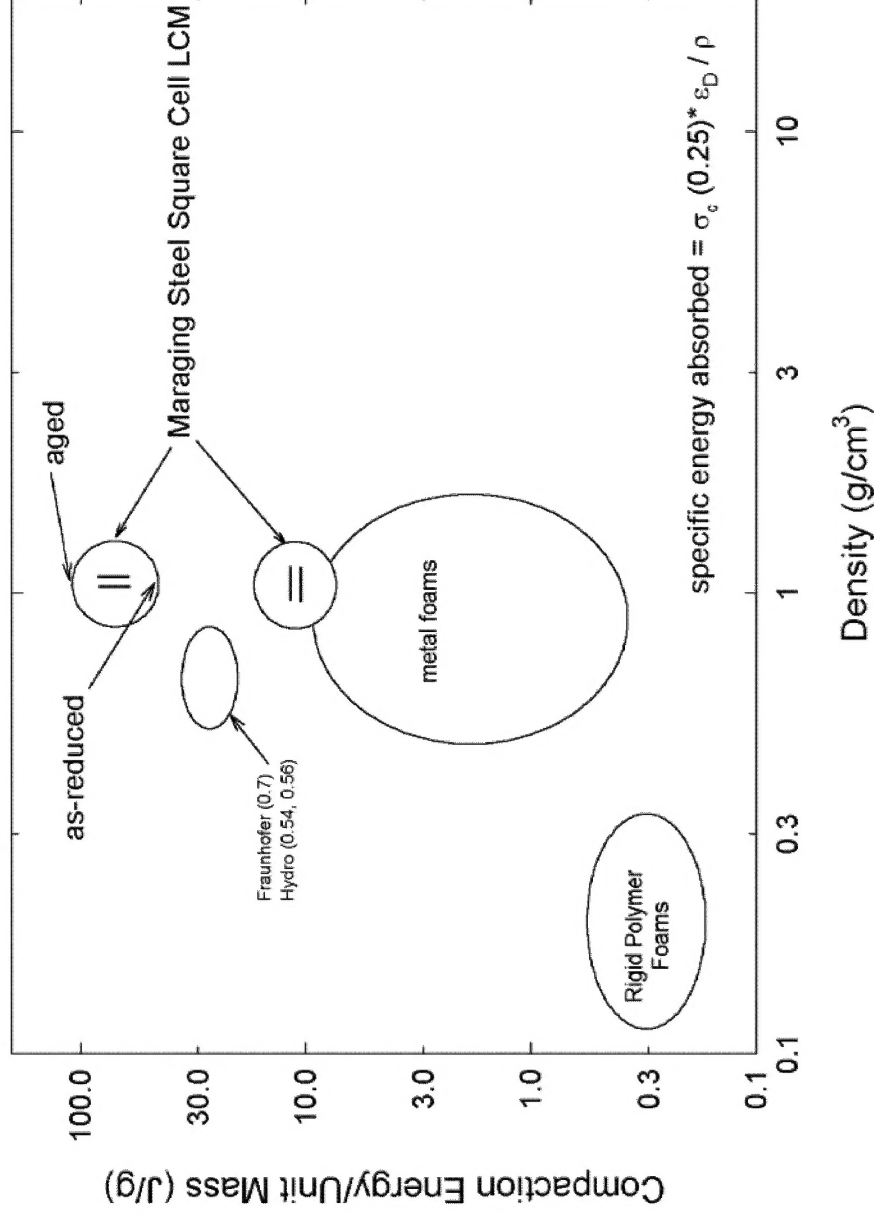
Compressive Strength Comparison: LCMs



Energy Absorption per Unit Mass



Specific Energy Absorption Comparison: LCM



CONCLUSIONS

Processing of High Conductivity Microchannel Linear Cellular Materials

- ! Models for paste properties and LCS die designs are nearing completion.
- ! Quality of honeycomb extrusion has improved dramatically and defects have been minimized.
- ! Metallurgical properties of alloys from direct oxide reduction can approach those of conventionally processed alloys.
- ! Due to low pressure drops and thin walls, high efficiency heat exchangers appear feasible for LCAs in a variety of applications.
- ! High energy adsorption for LCM in high strength alloys has been demonstrated.